

- Processed to MIL-PRF-38535 (QML)
- Operating Temperature Ranges:
 - Military (M) –55°C to 125°C
 - Special (S) –55°C to 105°C
- SMD Approval
- High-Performance Floating-Point Digital Signal Processor (DSP):
 - SMJ320C31-60 (5 V)
33-ns Instruction Cycle Time
330 Million Operations Per Second (MOPS), 60 Million Floating-Point Operations Per Second (MFLOPS), 30 Million Instructions Per Second (MIPS)
 - SMJ320C31-50 (5 V)
40-ns Instruction Cycle Time
275 MOPS, 50 MFLOPS, 25 MIPS
 - SMJ320C31-40 (5 V)
50-ns Instruction Cycle Time
220 MOPS, 40 MFLOPS, 20 MIPS
 - SMJ320LC31-40 (3.3 V)
50-ns Instruction Cycle Time
220 MOPS, 40 MFLOPS, 20 MIPS
 - SMQ320LC31-40 (3.3 V)
50-ns Instruction Cycle Time
220 MOPS, 40 MFLOPS, 20 MIPS
- 32-Bit High-Performance CPU
- 16-/32-Bit Integer and 32-/40-Bit Floating-Point Operations
- 32-Bit Instruction and Data Words, 24-Bit Addresses
- Two 1K Word × 32-Bit Single-Cycle Dual-Access On-Chip RAM Blocks
- Boot-Program Loader
- 64-Word × 32-Bit Instruction Cache
- Eight Extended-Precision Registers
- Two Address Generators With Eight Auxiliary Registers and Two Auxiliary Register Arithmetic Units (ARAOUs)
- Two Low-Power Modes
- On-Chip Memory-Mapped Peripherals:
 - One Serial Port Supporting 8-/16-/24-/32-Bit Transfers
 - Two 32-Bit Timers
 - One-Channel Direct Memory Access (DMA) Coprocessor for Concurrent I/O and CPU Operation
- Fabricated Using Enhanced Performance Implanted CMOS (EPIC™) Technology by Texas Instruments (TI)
- Two- and Three-Operand Instructions
- 40 / 32-Bit Floating-Point / Integer Multiplier and Arithmetic Logic Unit (ALU)
- Parallel ALU and Multiplier Execution in a Single Cycle
- Block-Repeat Capability
- Zero-Overhead Loops With Single-Cycle Branches
- Conditional Calls and Returns
- Interlocked Instructions for Multiprocessing Support
- Bus-Control Registers Configure Strobe-Control Wait-State Generation
- Validated Ada Compiler
- Integer, Floating-Point, and Logical Operations
- 32-Bit Barrel Shifter
- One 32-Bit Data Bus (24-Bit Address)
- Packaging
 - 132-Lead Ceramic Quad Flatpack With Nonconductive Tie-Bar (HFG Suffix)
 - 141-Pin Ceramic Staggered Pin Grid-Array Package (GFA Suffix)
 - 132-Lead TAB Frame
 - 132-Lead Plastic Quad Flatpack (PQ Suffix)

description

The SMJ320C31, SMJ320LC31, and SMQ320LC31 digital signal processors (DSPs) are 32-bit, floating-point processors manufactured in 0.6- μ m triple-level-metal CMOS technology. The devices are part of the SMJ320C3x generation of DSPs from Texas Instruments.



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SMJ320C31, SMJ320LC31, SMQ320LC31 DIGITAL SIGNAL PROCESSORS

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description (continued)

The SMJ320C3x internal busing and special digital-signal-processing instruction set have the speed and flexibility to execute up to 60 MFLOPS. The SMJ320C3x optimizes speed by implementing functions in hardware that other processors implement through software or microcode. This hardware-intensive approach provides performance previously unavailable on a single chip.

The SMJ320C3x can perform parallel multiply and ALU operations on integer or floating-point data in a single cycle. Each processor also possesses a general-purpose register file, a program cache, dedicated ARAUs, internal dual-access memories, one DMA channel supporting concurrent I/O, and a short machine-cycle time. High performance and ease of use are results of these features.

General-purpose applications are greatly enhanced by the large address space, multiprocessor interface, internally and externally generated wait states, one external interface port, two timers, one serial port, and multiple-interrupt structure. The SMJ320C3x supports a wide variety of system applications from host processor to dedicated coprocessor.

High-level-language support is easily implemented through a register-based architecture, large address space, powerful addressing modes, flexible instruction set, and well-supported floating-point arithmetic.

For additional information when designing for cold temperature operation, please see Texas Instruments application report *320C3x, 320C4x and 320MCM42x Power-up Sensitivity at Cold Temperature*, literature number SGUA001.

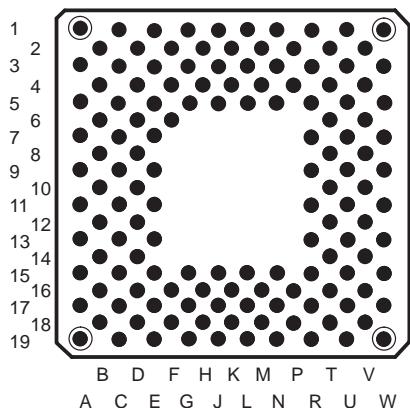


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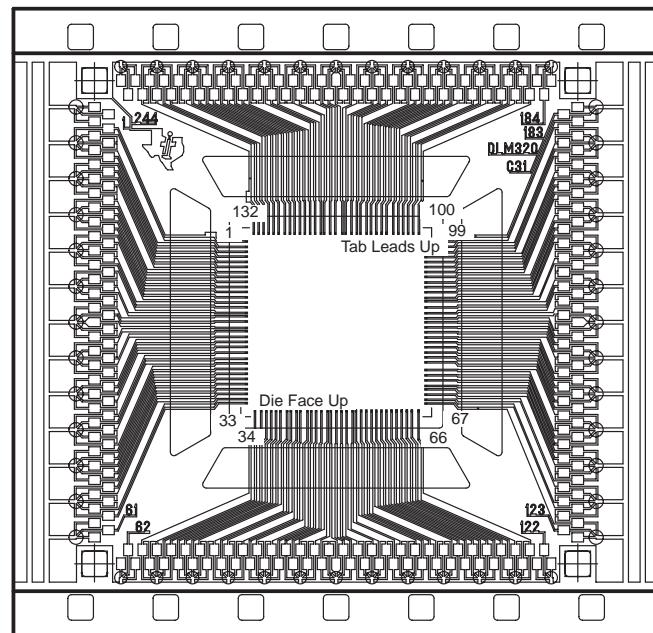
SMJ320C31, SMJ320LC31, SMQ320LC31 DIGITAL SIGNAL PROCESSORS

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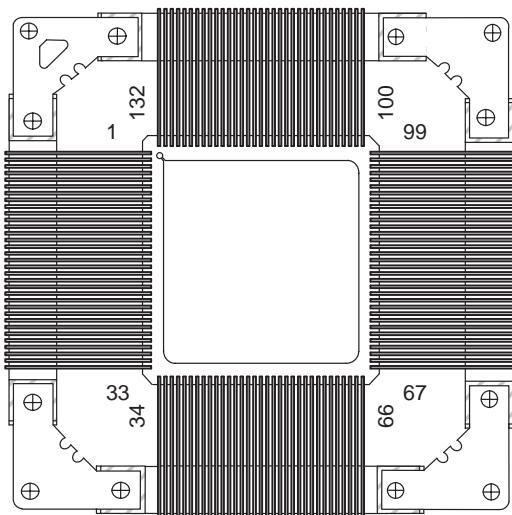
141-PIN GFA STAGGERED GRID ARRAY
PACKAGE
(BOTTOM VIEW)



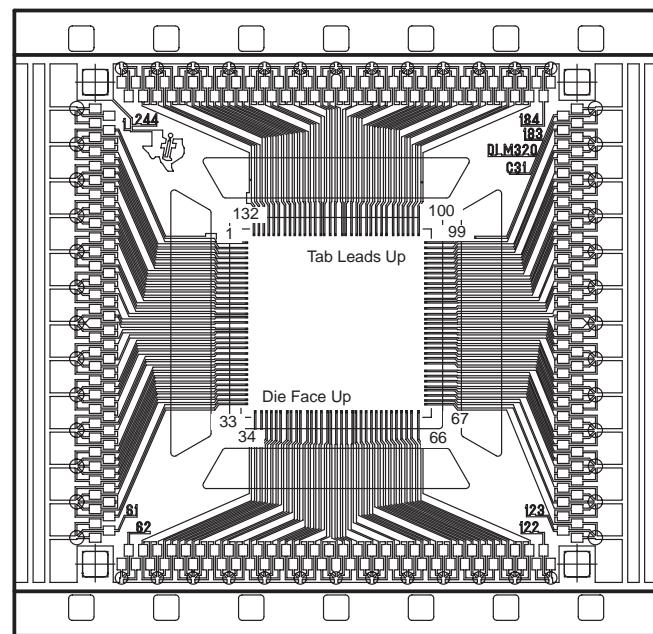
TA PACKAGE
(TOP VIEW)



132-PIN HFG QUAD FLATPACK
(TOP VIEW)



TB PACKAGE
(TOP VIEW)



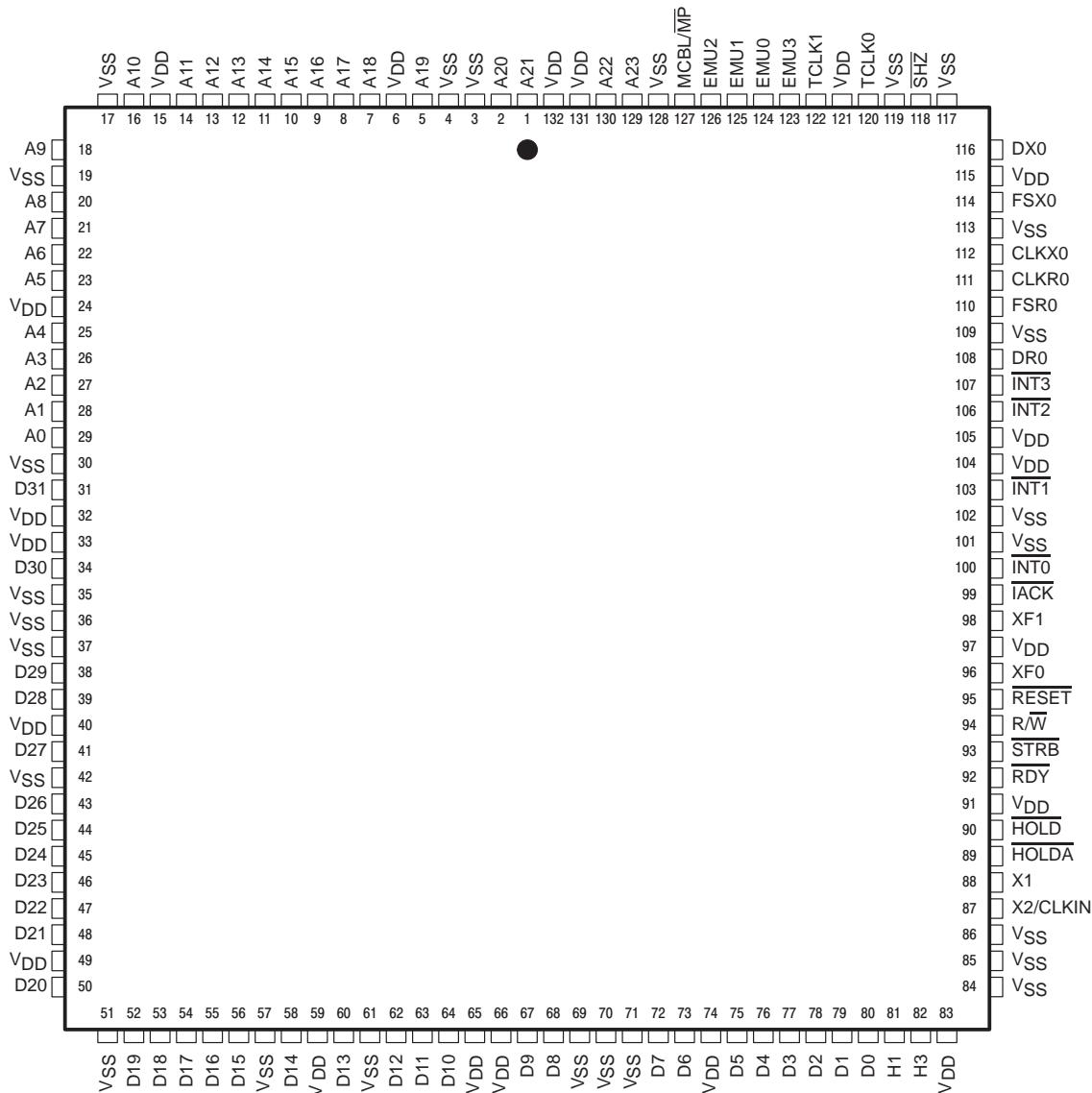
SMJ320C31, SMJ320LC31, SMQ320LC31 DIGITAL SIGNAL PROCESSORS

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SMQ320LC31 pinout (top view)

The SMQ320LC31 device is also packaged in a132-pin plastic quad flatpack (PQ Suffix). The full part numbers are SMQ320LC31PQM40 and 5962-9760601NXB.

**PQ PACKAGE
(TOP VIEW)**



Terminal Assignments

| PIN | | | PIN | | |
|-----------|------------|------|-----------|------------|------|
| NUMBER | | NAME | NUMBER | | NAME |
| PQ PKG | HFG PKG | | PQ PKG | HFG PKG | |
| 29 | 12 | L1 | A0 | 64 | W9 |
| 28 | 11 | K2 | A1 | 63 | U9 |
| 27 | 10 | J1 | A2 | 62 | V8 |
| 26 | 9 | J3 | A3 | 60 | W7 |
| 25 | 8 | G1 | A4 | 58 | U7 |
| 23 | 6 | F2 | A5 | 56 | V6 |
| 22 | 5 | E1 | A6 | 55 | W5 |
| 21 | 4 | E3 | A7 | 54 | U5 |
| 20 | 3 | D2 | A8 | 53 | V4 |
| 18 | 1 | C1 | A9 | 52 | W3 |
| 16 | 131 | C3 | A10 | 50 | U3 |
| 14 | 129 | B2 | A11 | 48 | V2 |
| 13 | 128 | A1 | A12 | 47 | W1 |
| 12 | 127 | C5 | A13 | 46 | R3 |
| 11 | 126 | B4 | A14 | 45 | T2 |
| 10 | 125 | A3 | A15 | 44 | U1 |
| 9 | 124 | C7 | A16 | 43 | N3 |
| 8 | 123 | B6 | A17 | 41 | P2 |
| 7 | 122 | C9 | A18 | 39 | R1 |
| 5 | 120 | B8 | A19 | 38 | L3 |
| 2 | 117 | A7 | A20 | 34 | M2 |
| 1 | 116 | A9 | A21 | 31 | N1 |
| 130 | 113 | B10 | A22 | 108 | C19 |
| 129 | 112 | A11 | A23 | 116 | C17 |
| 111 | 94 | E17 | CLKR0 | 124 | B14 |
| 112 | 95 | A19 | CLKX0 | 125 | EMU0 |
| 80 | 63 | W19 | D0 | 126 | DX0 |
| 79 | 62 | V16 | D1 | 123 | EMU1 |
| 78 | 61 | W17 | D2 | 110 | 109 |
| 77 | 60 | U13 | D3 | 114 | 108 |
| 76 | 59 | V14 | D4 | 81 | 107 |
| 75 | 58 | W15 | D5 | 82 | 106 |
| 73 | 56 | U11 | D6 | 90 | 105 |
| 72 | 55 | V12 | D7 | 89 | 104 |
| 68 | 51 | W11 | D8 | 99 | 103 |
| 67 | 50 | V10 | D9 | 100 | 102 |

† CV_{SS}, V_{SSSL}, and IV_{SS} are on the same plane.

‡ AV_{DD}, DV_{DD}, CV_{DD}, and PV_{DD} are on the same plane.

§ V_{SUBS} connects to die metallization. Tie this pin to clean ground.

SMJ320C31, SMJ320LC31, SMQ320LC31 DIGITAL SIGNAL PROCESSORS

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Terminal Assignments (Continued)

| PIN | | | PIN | | | NAME | |
|-----------|------------|------|-------------------------------|------------|------------|------|--------------------------------|
| NUMBER | | NAME | NUMBER | | NAME | | |
| PQ PKG | HFG PKG | | PQ PKG | HFG PKG | GFA PKG | | |
| 103 | 86 | E19 | INT1 | 30 | 18 | P4 | VSSL [†] |
| 106 | 89 | F18 | INT2 | 35 | 19 | T10 | VSSL [†] |
| 107 | 90 | G17 | INT3 | 36 | 20 | K4 | DVSS |
| 127 | 110 | C11 | MCBL/MP | 37 | 25 | T4 | IVSS [†] |
| 92 | 77 | L19 | R/W | 42 | 34 | G3 | DVSS |
| 95 | 75 | N17 | RDY | 51 | 40 | K16 | CVSS [†] |
| 94 | 78 | K18 | RESET | 57 | 44 | T8 | IVSS [†] |
| 118 | 101 | A17 | SHZ | 61 | 52 | T12 | DVSS |
| 93 | 76 | M18 | STRB | 69 | 53 | R11 | VSSL [†] |
| 120 | 103 | B16 | TCLK0 | 70 | 54 | J15 | VSSL [†] |
| | 105 | C15 | TCLK1 | 71 | 67 | W13 | DVSS |
| | 121 | G5 | AV _{DD} [‡] | 84 | 68 | D10 | CVSS [†] |
| 6 | 130 | E7 | AV _{DD} [‡] | 85 | 69 | D16 | IVSS [†] |
| 15 | 7 | E5 | AV _{DD} [‡] | 86 | 84 | T16 | DVSS |
| 24 | 15 | N5 | V _{DDL} | 101 | 85 | D12 | VSSL [†] |
| 32 | 16 | R5 | V _{DDL} | 102 | 92 | F16 | CVSS [†] |
| 33 | 23 | H4 | DV _{DD} [‡] | 109 | 96 | H16 | IVSS [†] |
| 40 | 32 | J5 | DV _{DD} [‡] | 113 | 100 | D14 | V _{SUBS} [§] |
| 49 | 42 | T14 | DV _{DD} [‡] | 117 | 102 | U15 | DVSS |
| 59 | 48 | R7 | V _{DDL} | 119 | 111 | C13 | CVSS [†] |
| 65 | 49 | R9 | V _{DDL} | 128 | 71 | T18 | X1 |
| 66 | 57 | R13 | DV _{DD} [‡] | 88 | 70 | U19 | X2/CLKIN |
| 74 | 66 | R15 | DV _{DD} [‡] | 87 | 79 | J19 | XF0 |
| 83 | 74 | P16 | CV _{DD} [‡] | 96 | 81 | G19 | XF1 |
| 91 | 80 | N15 | CV _{DD} [‡] | 98 | | F6 | No Connect |
| 97 | 87 | G15 | V _{DDL} | | | D4 | DVSS |
| 104 | 88 | E15 | V _{DDL} | | | N19 | DVSS |
| 105 | 98 | L15 | PV _{DD} [‡] | | | R17 | DVSS |
| 115 | 104 | E9 | PV _{DD} [‡] | | | L17 | DVSS |
| 121 | 114 | E13 | V _{DDL} | | | M16 | DVSS |
| 131 | 115 | E11 | V _{DDL} | | | D6 | DVSS |
| 132 | 118 | L5 | V _{SSL} [†] | | | A5 | DVSS |
| 3 | 119 | H2 | DVSS | | | D8 | DVSS |
| 4 | 132 | M4 | CV _{SS} [†] | | | | |
| 17 | 2 | F4 | DV _{SS} | | | | |
| 19 | 13 | T6 | CV _{SS} [†] | | | | |

[†] CV_{SS}, V_{SSL}, and IV_{SS} are on the same plane.

[‡] AV_{DD}, DV_{DD}, CV_{DD}, and PV_{DD} are on the same plane.

[§] V_{SUBS} connects to die metallization. Tie this pin to clean ground.

Terminal Functions

| TERMINAL NAME | QTY | TYPE† | DESCRIPTION | CONDITIONS WHEN SIGNAL IS Z TYPE‡ |
|------------------------------|-----|-------|---|---|
| PRIMARY-BUS INTERFACE | | | | |
| D31–D0 | 32 | I/O/Z | 32-bit data port | S H R |
| A23–A0 | 24 | O/Z | 24-bit address port | S H R |
| R/W | 1 | O/Z | Read/write. R/W is high when a read is performed and low when a write is performed over the parallel interface. | S H R |
| STRB | 1 | O/Z | External-access strobe | S H |
| RDY | 1 | I | Ready. RDY indicates that the external device is prepared for a transaction completion. | |
| HOLD | 1 | I | Hold. When HOLD is a logic low, any ongoing transaction is completed. A23–A0, D31–D0, STRB, and R/W are placed in the high-impedance state and all transactions over the primary-bus interface are held until HOLD becomes a logic high or until the NOHOLD bit of the primary-bus-control register is set. | |
| HOLDA | 1 | O/Z | Hold acknowledge. HOLDA is generated in response to a logic low on HOLD. HOLDA indicates that A23–A0, D31–D0, STRB, and R/W are in the high-impedance state and that all transactions over the bus are held. HOLDA is high in response to a logic high of HOLD or the NOHOLD bit of the primary-bus-control register is set. | S |
| CONTROL SIGNALS | | | | |
| RESET | 1 | I | Reset. When RESET is a logic low, the device is in the reset condition. When RESET becomes a logic high, execution begins from the location specified by the reset vector. | |
| INT3–INT0 | 4 | I | External interrupts | |
| IACK | 1 | O/Z | Interrupt acknowledge. IACK is generated by the IACK instruction. IACK can be used to indicate the beginning or the end of an interrupt-service routine. | S |
| MCBL/MP | 1 | I | Microcomputer boot-loader/microprocessor mode-select | |
| SHZ | 1 | I | Shutdown high impedance. When active, SHZ shuts down the device and places all pins in the high-impedance state. SHZ is used for board-level testing to ensure that no dual-drive conditions occur. CAUTION: A low on SHZ corrupts the device memory and register contents. Reset the device with SHZ high to restore it to a known operating condition. | |
| XF1, XF0 | 2 | I/O/Z | External flags. XF1 and XF0 are used as general-purpose I/Os or to support interlocked processor instruction. | S R |
| SERIAL PORT 0 SIGNALS | | | | |
| CLKR0 | 1 | I/O/Z | Serial port 0 receive clock. CLKR0 is the serial shift clock for the serial port 0 receiver. | S R |
| CLKX0 | 1 | I/O/Z | Serial port 0 transmit clock. CLKX0 is the serial shift clock for the serial port 0 transmitter. | S R |
| DR0 | 1 | I/O/Z | Data-receive. Serial port 0 receives serial data on DR0. | S R |
| DX0 | 1 | I/O/Z | Data-transmit output. Serial port 0 transmits serial data on DX0. | S R |
| FSR0 | 1 | I/O/Z | Frame-synchronization pulse for receive. The FSR0 pulse initiates the data-receive process using DR0. | S R |
| FSX0 | 1 | I/O/Z | Frame-synchronization pulse for transmit. The FSX0 pulse initiates the data-transmit process using DX0. | S R |
| TIMER SIGNALS | | | | |
| TCLK0 | 1 | I/O/Z | Timer clock 0. As an input, TCLK0 is used by timer 0 to count external pulses. As an output, TCLK0 outputs pulses generated by timer 0. | S |
| TCLK1 | 1 | I/O/Z | Timer clock 1. As an input, TCLK1 is used by timer 1 to count external pulses. As an output, TCLK1 outputs pulses generated by timer 1. | S |

† I = input, O = output, Z = high-impedance state

‡ S = SHZ active, H = HOLD active, R = RESET active

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Terminal Functions (Continued)

| TERMINAL NAME | QTY | TYPE [†] | DESCRIPTION | CONDITIONS WHEN SIGNAL IS Z TYPE [‡] |
|--------------------------------------|-----|-------------------|--|---|
| SUPPLY AND OSCILLATOR SIGNALS | | | | |
| H1 | 1 | O/Z | External H1 clock. H1 has a period equal to twice CLKIN. | S |
| H3 | 1 | O/Z | External H3 clock. H3 has a period equal to twice CLKIN. | S |
| V _{DD} | 20 | I | 5-V supply for 'C31 devices and 3.3-V supply for 'LC31 devices. All must be connected to a common supply plane. [§] | |
| V _{SS} | 25 | I | Ground. All grounds must be connected to a common ground plane. | |
| X1 | 1 | O | Output from the internal-crystal oscillator. If a crystal is not used, X1 should be left unconnected. | |
| X2/CLKIN | 1 | I | Internal-oscillator input from a crystal or a clock | |
| RESERVED[¶] | | | | |
| EMU2–EMU0 | 3 | I | Reserved for emulation. Use pullup resistors to V _{DD} | |
| EMU3 | 1 | O/Z | Reserved for emulation | S |

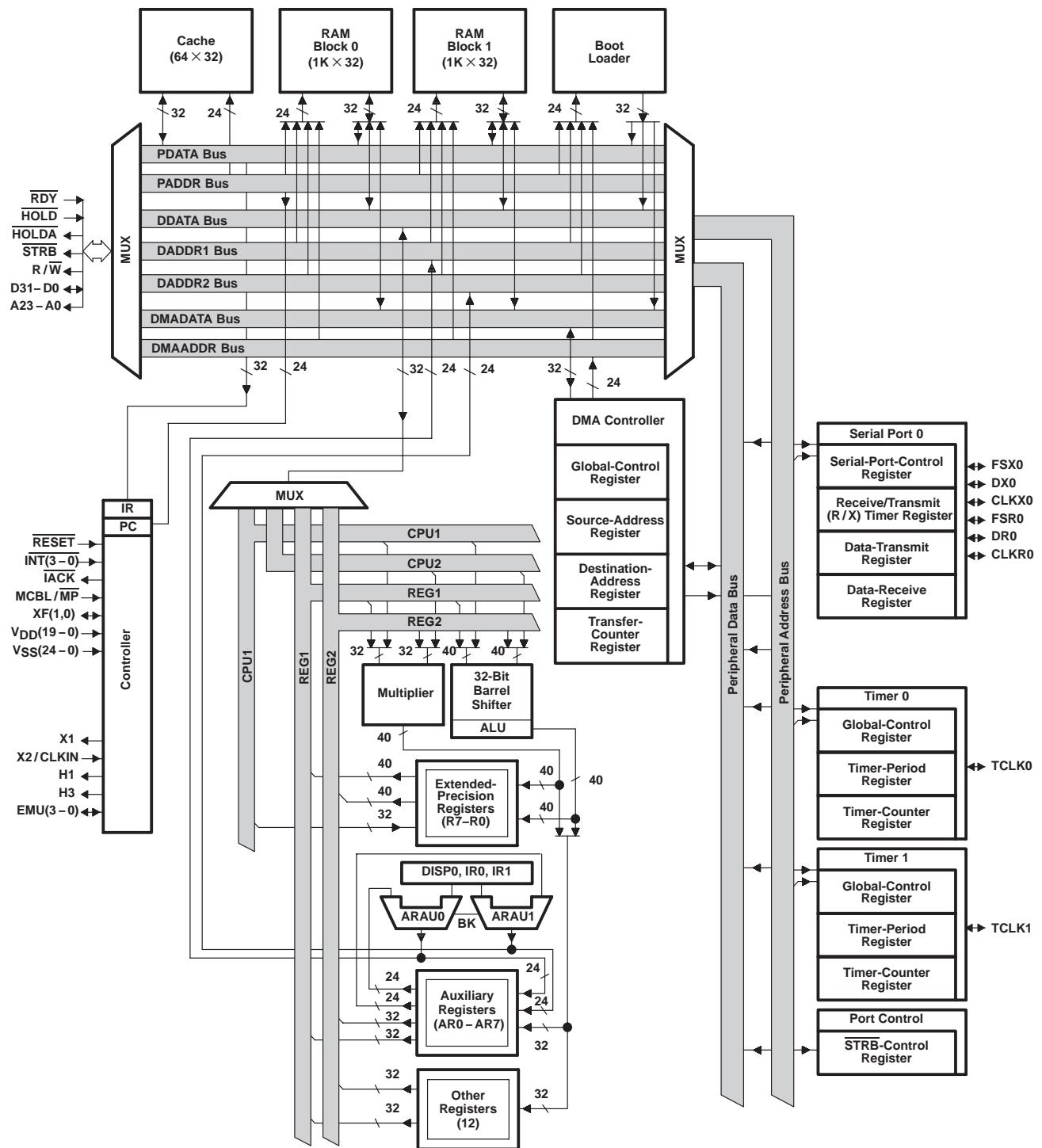
[†]I = input, O = output, Z = high-impedance state

[‡]S = SHZ active, H = HOLD active, R = RESET active

[§]Recommended decoupling capacitor value is 0.1 μ F.

[¶]Follow the connections specified for the reserved pins. Use 18-k Ω –22-k Ω pullup resistors for best results. All V_{DD} supply pins must be connected to a common supply plane, and all ground pins must be connected to a common ground plane.

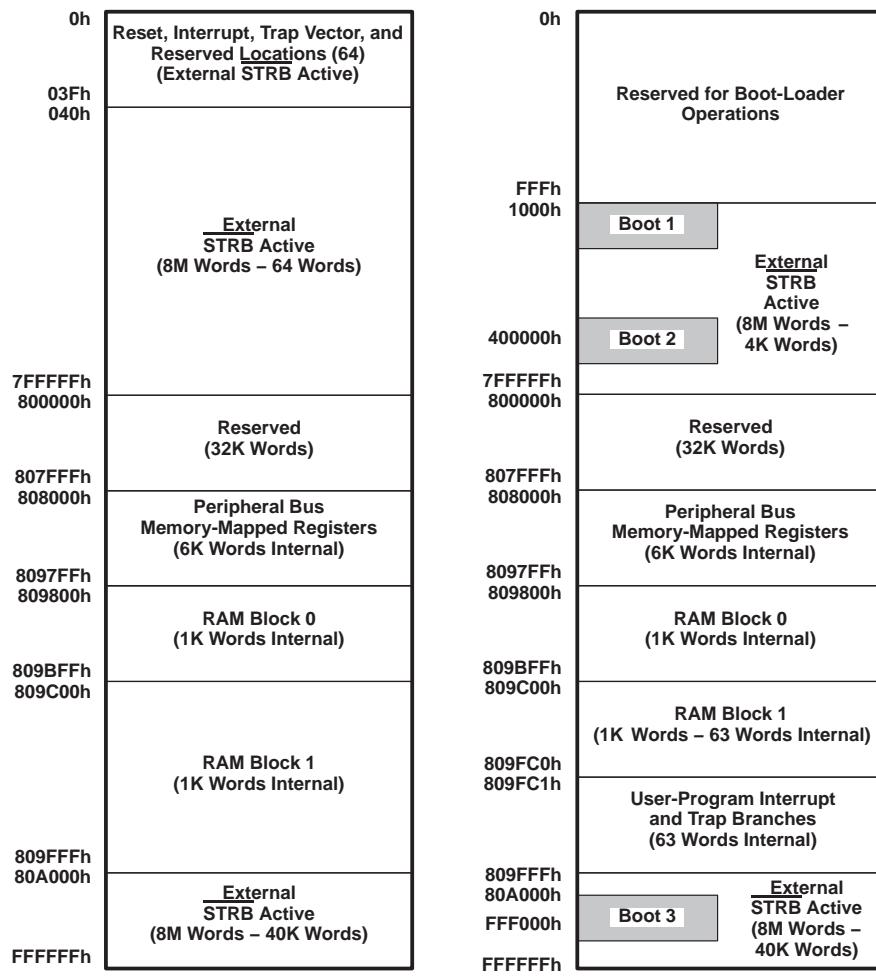
functional block diagram



SMJ320C31, SMJ320LC31, SMQ320LC31 DIGITAL SIGNAL PROCESSORS

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memory map†



† Figure 1 depicts the memory map for the SMJ320C31. See the *TMS320C3x Users Guide* (literature number SPRU031) for a detailed description of this memory mapping.

Figure 1. SMJ320C31 Memory Map

memory map (continued)

| | |
|-----|----------|
| 00h | Reset |
| 01h | INT0 |
| 02h | INT1 |
| 03h | INT2 |
| 04h | INT3 |
| 05h | XINT0 |
| 06h | RINT0 |
| 07h | Reserved |
| 08h | |
| 09h | TINT0 |
| 0Ah | TINT1 |
| 0Bh | DINT |
| 0Ch | Reserved |
| 1Fh | |
| 20h | TRAP 0 |
| | ● |
| | ● |
| | ● |
| 3Bh | TRAP 27 |
| 3Ch | Reserved |
| 3Fh | |

(a) Microprocessor Mode

| | |
|---------|----------|
| 809FC1h | INT0 |
| 809FC2h | INT1 |
| 809FC3h | INT2 |
| 809FC4h | INT3 |
| 809FC5h | XINT0 |
| 809FC6h | RINT0 |
| 809FC7h | Reserved |
| 809FC8h | |
| 809FC9h | TINT0 |
| 809FCAh | TINT1 |
| 809FCBh | DINT |
| 809FCCh | Reserved |
| 809FDFh | |
| 809FE0h | TRAP 0 |
| | ● |
| | ● |
| | ● |
| 809FFBh | TRAP 27 |
| 809FFCh | Reserved |
| 809FFFh | |

(b) Microcomputer/Boot-Loader Mode

Figure 2. Reset, Interrupt, and Trap Vector/Branches Memory-Map Locations

SMJ320C31, SMJ320LC31, SMQ320LC31 DIGITAL SIGNAL PROCESSORS

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memory map (continued)

| | |
|---------|----------------------------------|
| 808000h | DMA Global Control |
| 808004h | DMA Source Address |
| 808006h | DMA Destination Address |
| 808008h | DMA Transfer Counter |
| 808020h | Timer 0 Global Control |
| 808024h | Timer 0 Counter |
| 808028h | Timer 0 Period Register |
| 808030h | Timer 1 Global Control |
| 808034h | Timer 1 Counter |
| 808038h | Timer 1 Period Register |
| 808040h | Serial Global Control |
| 808042h | FSX/DX/CLKX Serial Port Control |
| 808043h | FSR/DR/CLKR Serial Port Control |
| 808044h | Serial R/X Timer Control |
| 808045h | Serial R/X Timer Counter |
| 808046h | Serial R/X Timer Period Register |
| 808048h | Data-Transmit |
| 80804Ch | Data-Receive |
| 808064h | Primary-Bus Control |

†Shading denotes reserved address locations

Figure 3. Peripheral Bus Memory-Mapped Registers†

absolute maximum ratings over specified temperature range (unless otherwise noted)[†]

| | 'C31 | 'LC31 |
|--|-----------------------------|-------------------------------|
| Supply voltage, V_{DD} (see Note 1) | –0.3 V to 7 V | –0.3 V to 5 V |
| Input voltage, V_I | –0.3 V to 7 V | –0.3 V to 5 V |
| Output voltage, V_O | –0.3 V to 7 V | –0.3 V to 5 V |
| Continuous power dissipation (worst case) (see Note 2) | 1.7 W (for SMJ320C31-33) | 850 mW (for SMJ320LC31-33) |
| Operating case temperature, T_C | –55°C to 125°C | –55°C to 125°C |
| Storage temperature, T_{stg} | –65°C to 150°C | –65°C to 150°C |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to V_{SS} .

2. Actual operating power is less. This value was obtained under specially produced worst-case test conditions for the TMS320C31-33 and the TMS320LC31-33, which are not sustained during normal device operation. These conditions consist of continuous parallel writes of a checkerboard pattern to both primary and extension buses at the maximum rate possible. See normal (I_{CC}) current specification in the electrical characteristics table and also read *Calculation of TMS320C30 Power Dissipation Application Report* (literature number SPRA020).

recommended operating conditions (see Note 3)

| | | 'C31 | | | 'LC31 | | | UNIT |
|----------|---|-------------|-----|------------------|-------|-----|------------------|-------------|
| | | MIN | NOM | MAX | MIN | NOM | MAX | |
| V_{DD} | Supply voltage (DV_{DD} , etc.) | 4.75 | 5 | 5.25 | 3.13 | 3.3 | 3.47 | V |
| V_{SS} | Supply voltage (CV_{SS} , etc.) | | 0 | | | 0 | | V |
| V_{IH} | High-level input voltage (except \overline{RESET}) | 2.1 | | $V_{DD} + 0.3^*$ | 1.8 | | $V_{DD} + 0.3^*$ | V |
| | High-level input voltage (\overline{RESET}) | 2.2 | | $V_{DD} + 0.3^*$ | 2.2 | | $V_{DD} + 0.3^*$ | V |
| V_{IL} | Low-level input voltage | –0.3* | | 0.8 | –0.3* | | 0.6 | V |
| I_{OH} | High-level output current | | | –300 | | | –300 | μA |
| I_{OL} | Low-level output current | | | 2 | | | 2 | mA |
| T_C | Operating case temperature | '320C31-40 | –55 | 125 | | | | $^{\circ}C$ |
| | | '320C31-50 | –55 | 125 | | | | |
| | | '320C31-60 | –55 | 105 | | | | |
| | | '320LC31-40 | | | –55 | | 125 | |
| V_{TH} | High-level input voltage for $CLKIN$ | 3.0 | | $V_{DD} + 0.3^*$ | 2.5 | | $V_{DD} + 0.3^*$ | V |

* This parameter is not production tested.

NOTE 3: All voltage values are with respect to V_{SS} . All input and output voltage levels are TTL-compatible. $CLKIN$ can be driven by a CMOS clock.

SMJ320C31, SMJ320LC31, SMQ320LC31 DIGITAL SIGNAL PROCESSORS

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**electrical characteristics over recommended ranges of supply voltage (unless otherwise noted)
(see Note 3)†**

| PARAMETER | TEST CONDITIONS | 'C31 | | | 'LC31 | | | UNIT |
|-----------------|--------------------------------------|---|-------------------------|---------------------|-------|------|-----|------|
| | | MIN | TYP‡ | MAX | MIN | TYP‡ | MAX | |
| V _{OH} | High-level output voltage | V _{DD} = MIN, I _{OH} = MAX | 2.4 | 3 | 2 | | | V |
| V _{OL} | Low-level output voltage | V _{DD} = MIN, I _{OH} = MAX | | 0.3 0.6 | | | 0.4 | V |
| I _Z | High-impedance current | V _{DD} = MAX | – 20 | + 20 | – 20 | + 20 | | µA |
| I _I | Input current | V _I = V _{SS} to V _{DD} | – 10 | + 10 | – 10 | + 10 | | µA |
| I _{IP} | Input current (with internal pullup) | Inputs with internal pullups§ | – 600 | 20 | – 600 | 10 | | µA |
| I _{CC} | Supply current¶# | T _A = 25°C, V _{DD} = MAX | f _X = 40 MHz | 'C31-40 'LC31-40 | 160 | 400 | 150 | 300 |
| | | | f _X = 50 MHz | 'C31-50 | 200 | 425 | | |
| | | | f _X = 60 MHz | 'C31-60 | 225 | 475 | | |
| I _{DD} | Supply current | Standby, IDLE2 Clocks shut off | | 50 | | 20 | | µA |
| C _i | Input capacitance | All inputs except CLKIN | | 15* | | 15* | | pF |
| | CLKIN | | | 25 | | 25 | | |
| C _o | Output capacitance | | | 20* | | 20* | | pF |

† All input and output voltage levels are TTL compatible.

‡ For 'C31, all typical values are at V_{DD} = 5 V, T_A = 25°C. For 'LC31, all typical values are at V_{DD} = 3.3 V, T_A = 25°C.

§ Pins with internal pullup devices: INT3–INT0, MCBL/MP.

¶ Actual operating current is less than this maximum value. This value was obtained under specially produced worst-case test conditions, which are not sustained during normal device operation. These conditions consist of continuous parallel writes of a checkerboard pattern to both primary and expansion buses at the maximum rate possible. See *Calculation of TMS320C30 Power Dissipation Application Report* (literature number SPRA020).

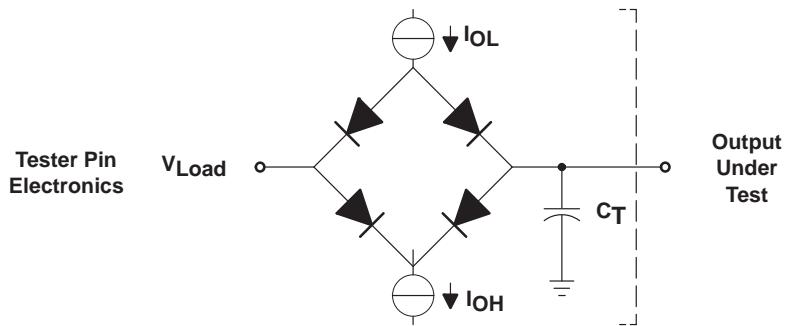
f_X is the input clock frequency.

* This parameter is not production tested.

NOTE 3: All voltage values are with respect to V_{SS}. All input and output voltage levels are TTL-compatible. CLKIN can be driven by a CMOS clock.



PARAMETER MEASUREMENT INFORMATION



Where: $I_{OL} = 2 \text{ mA}$ (all outputs)
 $I_{OH} = 300 \mu\text{A}$ (all outputs)
 V_{LOAD} = Selected to emulate $50\text{-}\Omega$ termination (typical value = 1.54 V).
 $C_T = 80\text{-pF}$ typical load-circuit capacitance

Figure 4. SMJ320C31 Test Load Circuit

signal transition levels for 'C31 (see Figure 5 and Figure 6)

TTL-level outputs are driven to a minimum logic-high level of 2.4 V and to a maximum logic-low level of 0.6 V. Output transition times are specified as follows:

- For a high-to-low transition on a TTL-compatible output signal, the level at which the output is said to be no longer high is 2 V and the level at which the output is said to be low is 1 V.
- For a low-to-high transition, the level at which the output is said to be no longer low is 1 V and the level at which the output is said to be high is 2 V.

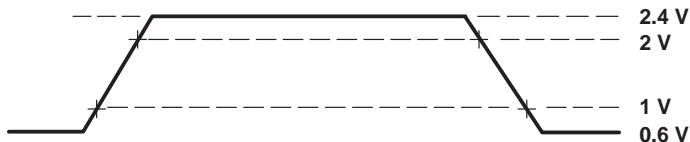


Figure 5. TTL-Level Outputs

Transition times for TTL-compatible inputs are specified as follows:

- For a high-to-low transition on an input signal, the level at which the input is said to be no longer high is 2.1 V and the level at which the input is said to be low is 0.8 V.
- For a low-to-high transition on an input signal, the level at which the input is said to be no longer low is 0.8 V and the level at which the input is said to be high is 2.1 V.

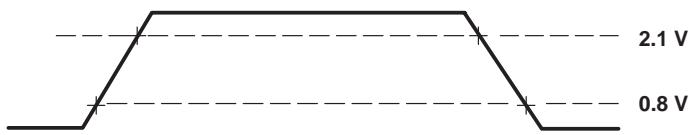
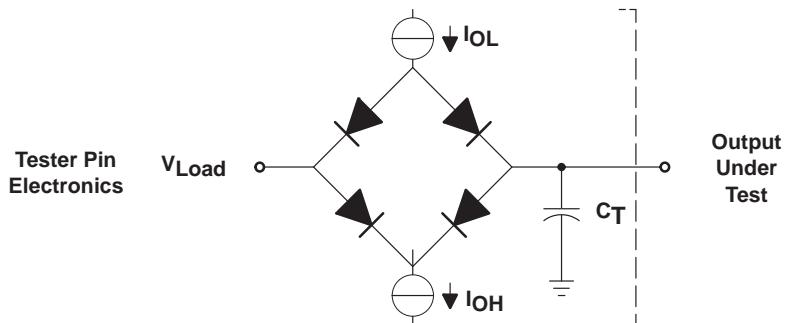


Figure 6. TTL-Level Inputs

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PARAMETER MEASUREMENT INFORMATION



Where: $I_{OL} = 2 \text{ mA}$ (all outputs)
 $I_{OH} = 300 \mu\text{A}$ (all outputs)
 $V_{LOAD} = 2.15 \text{ V}$
 $C_T = 80\text{-pF}$ typical load-circuit capacitance

Figure 7. SMJ320LC31 Test Load Circuit

signal transition levels for 'LC31 (see Figure 8 and Figure 9)

Outputs are driven to a minimum logic-high level of 2 V and to a maximum logic-low level of 0.4 V. Output transition times are specified as follows:

- For a high-to-low transition on an output signal, the level at which the output is said to be no longer high is 2 V and the level at which the output is said to be low is 1 V.
- For a low-to-high transition, the level at which the output is said to be no longer low is 1 V and the level at which the output is said to be high is 2 V.

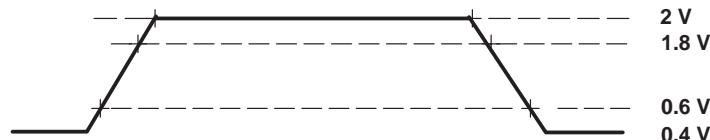


Figure 8. 'LC31 Output Levels

Transition times for inputs are specified as follows:

- For a high-to-low transition on an input signal, the level at which the input is said to be no longer high is 1.8 V and the level at which the input is said to be low is 0.6 V.
- For a low-to-high transition on an input signal, the level at which the input is said to be no longer low is 0.6 V and the level at which the input is said to be high is 1.8 V.

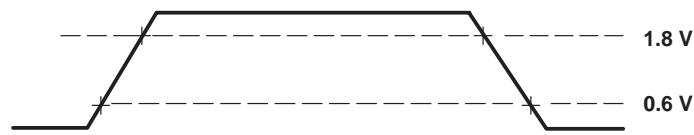


Figure 9. 'LC31 Input Levels

PARAMETER MEASUREMENT INFORMATION

timing parameter symbology

Timing parameter symbols used herein were created in accordance with JEDEC Standard 100-A. In order to shorten the symbols, some of the pin names and other related terminology have been abbreviated as follows, unless otherwise noted:

| | | | |
|---------|--|-------|--|
| A | A23–A0 | H | H1 and H3 |
| ASYNCH | Asynchronous reset signals | HOLD | <u>HOLD</u> |
| C | CLKX0 | HOLDA | <u>HOLDA</u> |
| CI | CLKIN | IACK | <u>IACK</u> |
| CLKR | CLKR0 | INT | <u>INT3–INT0</u> |
| CONTROL | Control signals | RDY | <u>RDY</u> |
| D | D31–D0 | RW | <u>R/W</u> |
| DR | DR | RESET | <u>RESET</u> |
| DX | DX | S | <u>STRB</u> |
| FS | FSX/R | SCK | CLKX/R |
| FSX | FSX0 | SHZ | <u>SHZ</u> |
| FSR | FSR0 | TCLK | TCLK0, TCLK1, or TCLKx |
| GPI | General-purpose input | XF | XF0, XF1, or XF _x |
| GPIO | General-purpose input/output; peripheral pin | XFIO | XF _x switching from input to output |
| GPO | General-purpose output | | |

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timing

Timing specifications apply to the SMJ320C31 and SMJ320LC31.

X2/CLKIN, H1, and H3 timing

The following table defines the timing parameters for the X2/CLKIN, H1, and H3 interface signals.

timing parameters for X2/CLKIN, H1, H3 (see Figure 10, Figure 11, Figure 12, and Figure 13)

| NO. | | 'C31-40 'LC31-40 | | 'C31-50 | | 'C31-60 | | UNIT |
|-----|--|---------------------|-----|---------|-----|---------|-----|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | |
| 1 | $t_f(Cl)$ Fall time, CLKIN | | | 5* | | 5* | 4* | ns |
| 2 | $t_w(CIL)$ Pulse duration, CLKIN low $t_c(Cl) = \text{min}$ | 9 | | 7 | | 6 | | ns |
| 3 | $t_w(CIH)$ Pulse duration, CLKIN high $t_c(Cl) = \text{min}$ | 9 | | 7 | | 6 | | ns |
| 4 | $t_r(Cl)$ Rise time, CLKIN | | | 5* | | 5* | 4* | ns |
| 5 | $t_c(Cl)$ Cycle time, CLKIN | 25 | 303 | 20 | 303 | 16.67 | 303 | ns |
| 6 | $t_f(H)$ Fall time, H1 and H3 | | | 3 | | 3 | 3 | ns |
| 7 | $t_w(HL)$ Pulse duration, H1 and H3 low | P-5† | | P-5† | | P-4† | | ns |
| 8 | $t_w(HH)$ Pulse duration, H1 and H3 high | P-6† | | P-6† | | P-5† | | ns |
| 9 | $t_r(H)$ Rise time, H1 and H3 | | | 3 | | 3 | 3 | ns |
| 10 | $t_d(HL-HH)$ Delay time, from H1 low to H3 high or from H3 low to H1 high | 0 | 4 | 0 | 4 | 0 | 4 | ns |
| 11 | $t_c(H)$ Cycle time, H1 and H3 | 50 | 606 | 40 | 606 | 33.3 | 606 | ns |

† $P = t_c(Cl)$

* This parameter is not production tested.

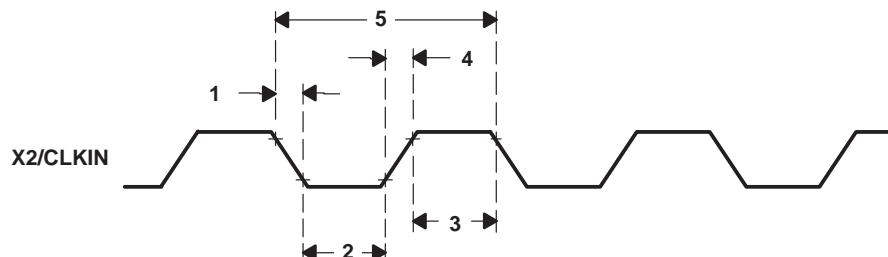


Figure 10. Timing for X2/CLKIN

X2/CLKIN, H1, and H3 timing (continued)

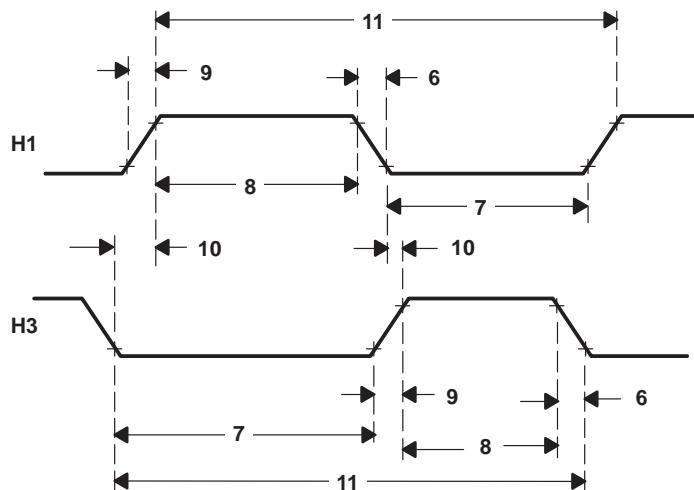
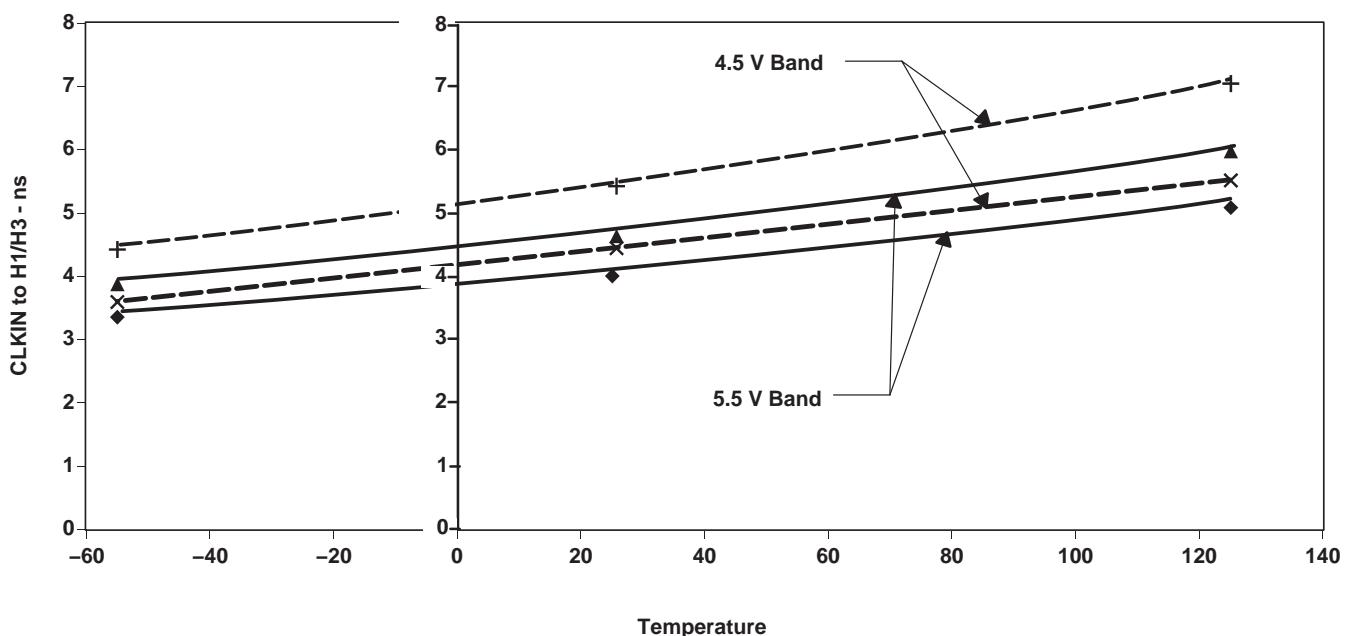


Figure 11. Timing for H1 and H3



**Figure 12. SMJ320C31 CLKIN to H1/H3 as a Function of Temperature
(Typical)**

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X2/CLKIN, H1, and H3 timing (continued)

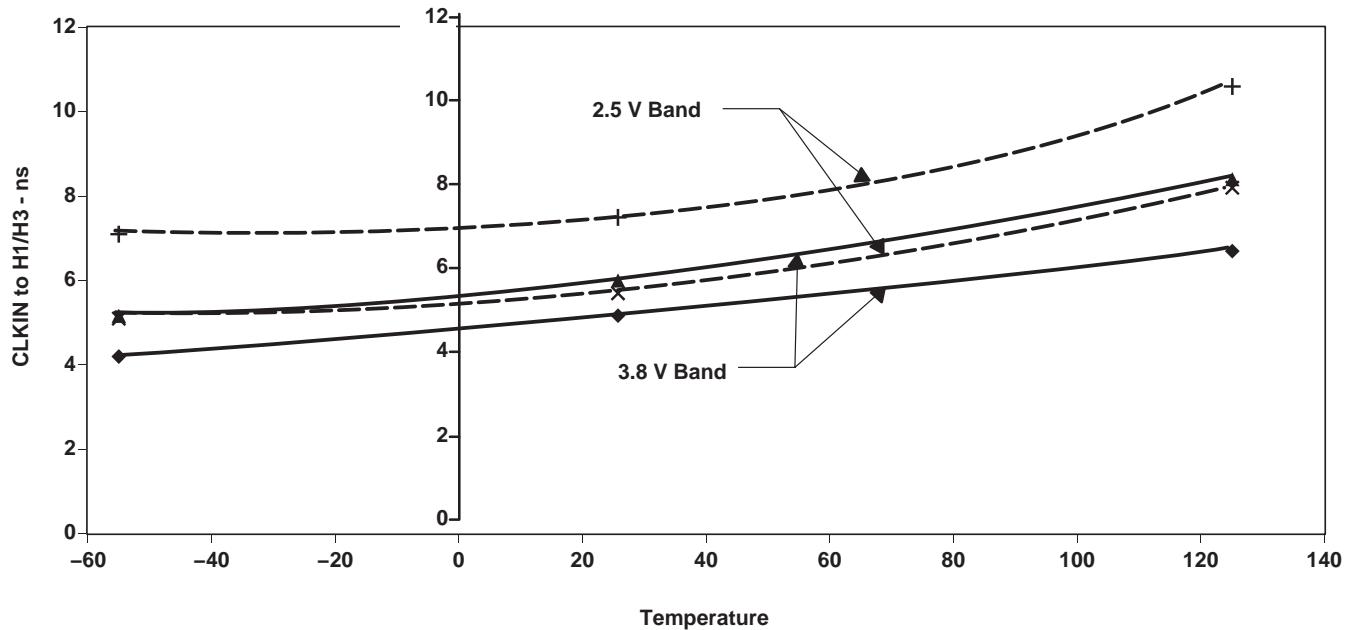


Figure 13. SMJ320LC31 CLKIN to H1/H3 as a Function of Temperature
(Typical)

memory read/write timing

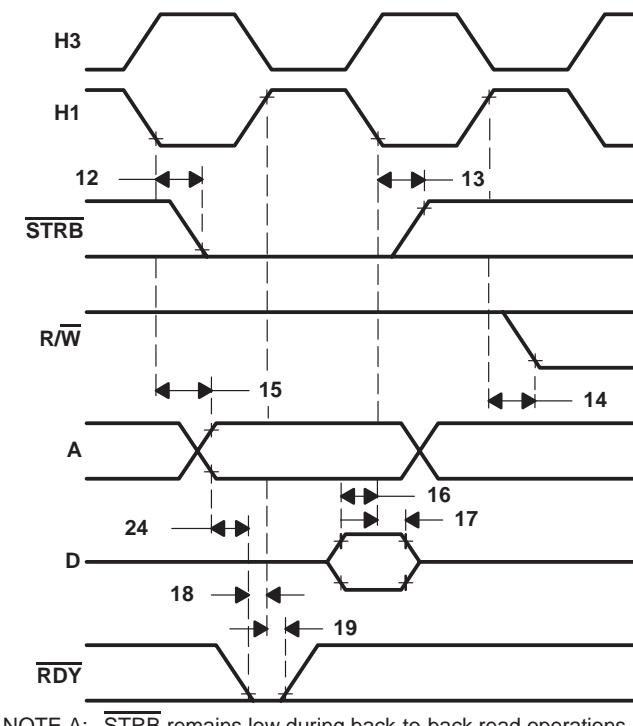
The following table defines memory read/write timing parameters for $\overline{\text{STRB}}$.

timing parameters for memory ($\overline{\text{STRB}} = 0$) read/write (see Figure 14 and Figure 15)[†]

| NO. | | 'C31-40 'LC31-40 | | 'C31-50 | | 'C31-60 | | UNIT | |
|-----|---------------------------------|---|-----|---------|-----|---------|-----|------|----|
| | | MIN | MAX | MIN | MAX | MIN | MAX | | |
| 12 | $t_{d(\text{H1L-SL})}$ | Delay time, H1 low to $\overline{\text{STRB}}$ low | 0* | 6 | 0* | 5 | 0* | 5 | ns |
| 13 | $t_{d(\text{H1L-SH})}$ | Delay time, H1 low to $\overline{\text{STRB}}$ high | 0* | 6 | 0* | 5 | 0* | 5 | ns |
| 14 | $t_{d(\text{H1H-RWL})\text{R}}$ | Delay time, H1 high to $\overline{\text{R/W}}$ low (read) | 0* | 9 | 0* | 7 | 0* | 6 | ns |
| 15 | $t_{d(\text{H1L-A})}$ | Delay time, H1 low to A valid | 0* | 10 | 0* | 10 | 0* | 8 | ns |
| 16 | $t_{su(\text{D-H1L})\text{R}}$ | Setup time, D before H1 low (read) | 14 | | 10 | | 9 | | ns |
| 17 | $t_{h(\text{H1L-D})\text{R}}$ | Hold time, D after H1 low (read) | 0 | | 0 | | 0 | | ns |
| 18 | $t_{su(\text{RDY-H1H})}$ | Setup time, $\overline{\text{RDY}}$ before H1 high | 8 | | 6 | | 5 | | ns |
| 19 | $t_{h(\text{H1H-RDY})}$ | Hold time, $\overline{\text{RDY}}$ after H1 high | 0 | | 0 | | 0 | | ns |
| 20 | $t_{d(\text{H1H-RWH})\text{W}}$ | Delay time, H1 high to $\overline{\text{R/W}}$ high (write) | | 9 | | 7 | | 6 | ns |
| 21 | $t_{v(\text{H1L-D})\text{W}}$ | Valid time, D after H1 low (write) | | 17 | | 14 | | 12 | ns |
| 22 | $t_{h(\text{H1H-D})\text{W}}$ | Hold time, D after H1 high (write) | 0 | | 0 | | 0 | | ns |
| 23 | $t_{d(\text{H1H-A})\text{W}}$ | Delay time, H1 high to A valid on back-to-back write cycles (write) | | 15 | | 14 | | 10 | ns |
| 24 | $t_{d(\text{A-RDY})}$ | Delay time, $\overline{\text{RDY}}$ from A valid | | 7* | | 6* | | 6* | ns |

[†] See Figure 16 for address bus timing variation with load capacitance greater than typical load-circuit capacitance ($C_T = 80 \text{ pF}$).

* This parameter is not production tested.



NOTE A: $\overline{\text{STRB}}$ remains low during back-to-back read operations.

Figure 14. Timing for Memory ($\overline{\text{STRB}} = 0$) Read

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memory read/write timing (continued)

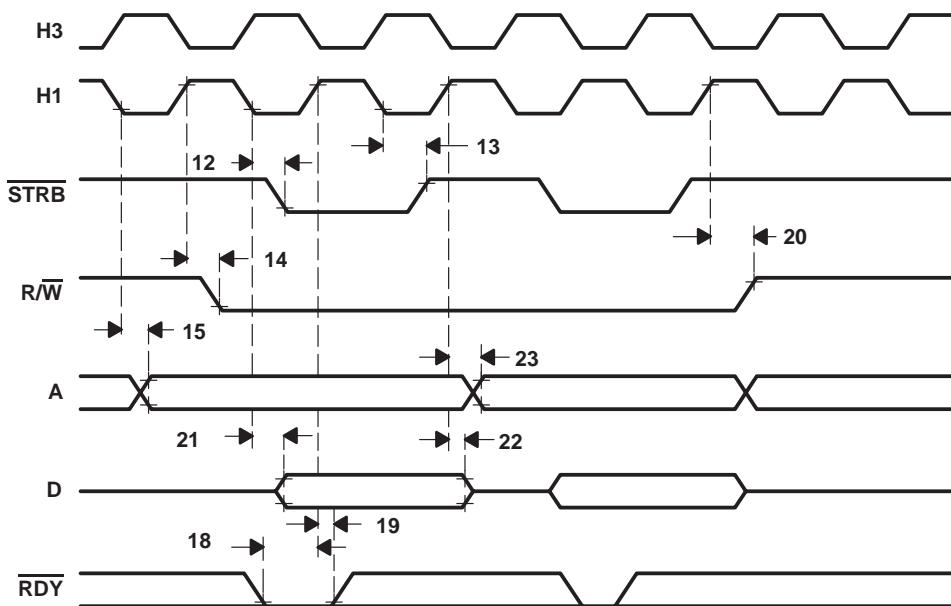
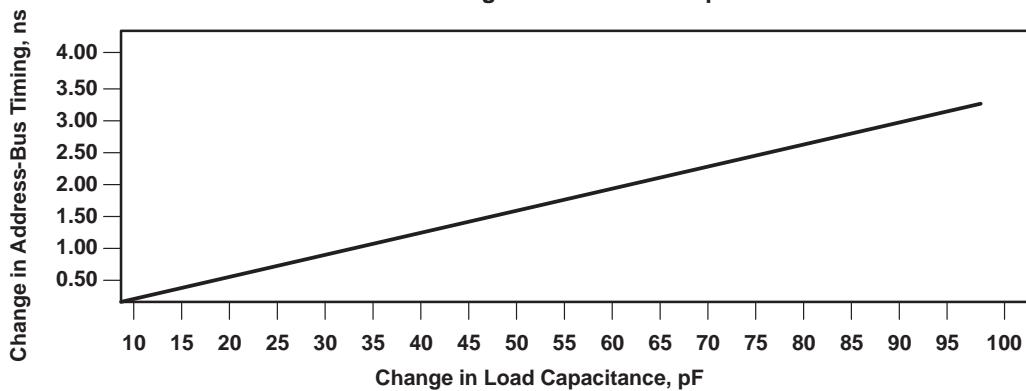


Figure 15. Timing for Memory ($\overline{\text{STRB}} = 0$) Write

Address-Bus Timing Variation Load Capacitance



NOTE A: 30 pF/ns slope

Figure 16. Address-Bus Timing Variation With Load Capacitance (see Note A)

XF0 and XF1 timing when executing LDFI or LDII

The following table defines the timing parameters for XF0 and XF1 during execution of LDFI or LDII.

timing for XF0 and XF1 when executing LDFI or LDII for SMJ320C31 (see Figure 17)

| NO. | | 'C31-40 | | 'LC31-40 | | 'C31-50 | | 'C31-60 | | UNIT |
|-----|---|---------|-----|----------|-----|---------|-----|---------|-----|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| 25 | $t_d(H3H-XF0L)$ Delay time, H3 high to XF0 low | | 13 | | 13 | | 12 | | 11 | ns |
| 26 | $t_{su}(XF1-H1L)$ Setup time, XF1 before H1 low | | 9 | | 10 | | 8 | | 8 | ns |
| 27 | $t_h(H1L-XF1)$ Hold time, XF1 after H1 low | | 0 | | 0 | | 0 | | 0 | ns |

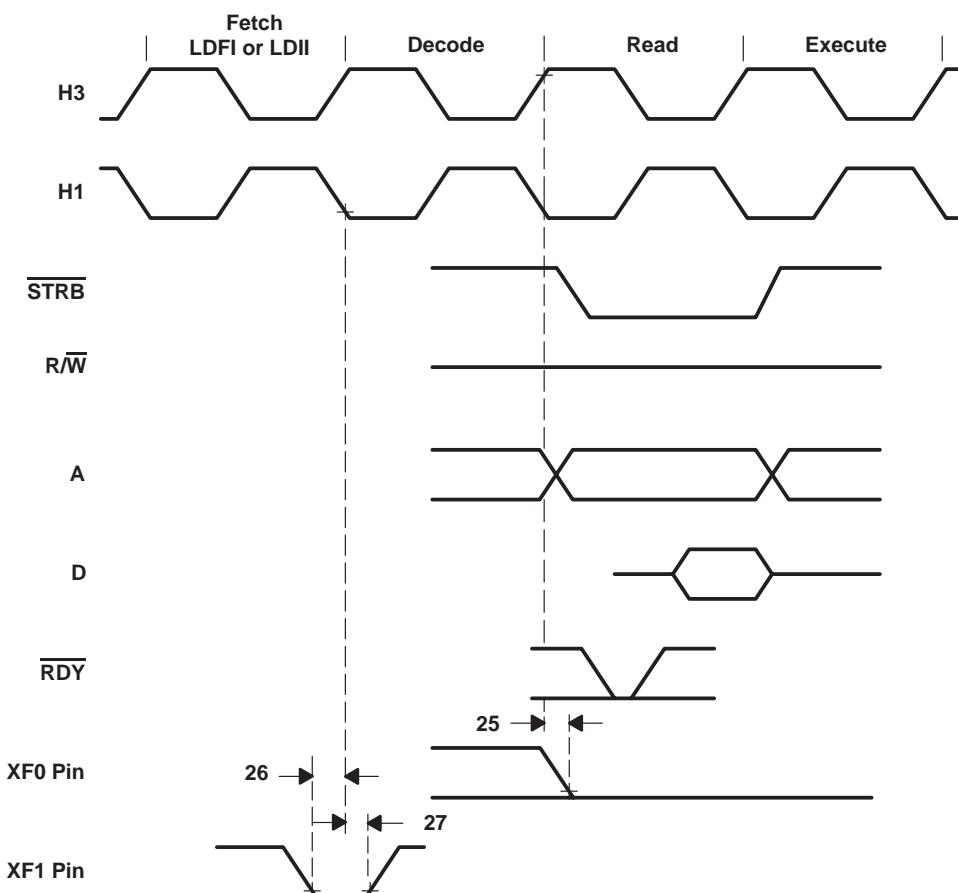


Figure 17. Timing for XF0 and XF1 When Executing LDFI or LDII

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XF0 timing when executing STFI and STII[†]

The following table defines the timing parameters for the XF0 pin during execution of STFI or STII.

timing for XF0 when executing STFI or STII (see Figure 18)

| NO. | | 'C31-40 'LC31-40 | | 'C31-50 | | 'C31-60 | | UNIT |
|-----|---|---------------------|-----|---------|-----|---------|-----|-------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | |
| 28 | $t_d(H3H-XF0H)$ Delay time, H3 high to XF0 high | | | 13 | | 12 | | 11 ns |

[†] XF0 is always set high at the beginning of the execute phase of the interlock-store instruction. When no pipeline conflicts occur, the address of the store is also driven at the beginning of the execute phase of the interlock-store instruction. However, if a pipeline conflict prevents the store from executing, the address of the store will not be driven until the store can execute.

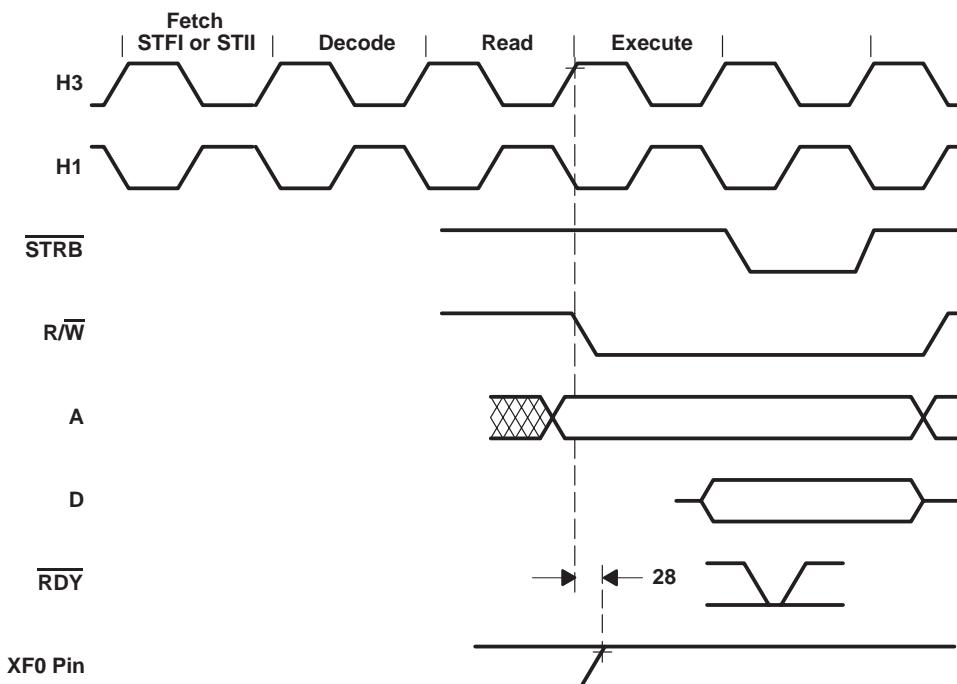


Figure 18. Timing for XF0 When Executing an STFI or STII

XF0 and XF1 timing when executing SIGI

The following table defines the timing parameters for the XF0 and XF1 pins during execution of SIGI.

timing for XF0 and XF1 when executing SIGI for SMJ320C31 (see Figure 19)

| NO. | | 'C31-40 | | 'LC31-40 | | 'C31-50 | | 'C31-60 | | UNIT |
|-----|-------------------|---------------------------------|-----|----------|-----|---------|-----|---------|-----|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| 29 | $t_d(H3H-XF0L)$ | Delay time, H3 high to XF0 low | 13 | 13 | 13 | 12 | 12 | 11 | 11 | ns |
| 30 | $t_d(H3H-XF0H)$ | Delay time, H3 high to XF0 high | 13 | 13 | 13 | 12 | 12 | 11 | 11 | ns |
| 31 | $t_{su}(XF1-H1L)$ | Setup time, XF1 before H1 low | 9 | 10 | 10 | 8 | 8 | 8 | 8 | ns |
| 32 | $t_h(H1L-XF1)$ | Hold time, XF1 after H1 low | 0 | 0 | 0 | 0 | 0 | 0 | 0 | ns |

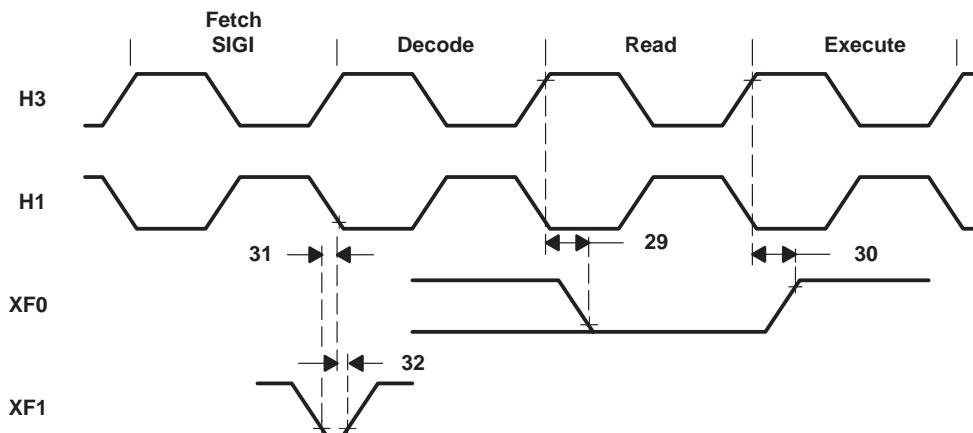


Figure 19. Timing for XF0 and XF1 When Executing SIGI

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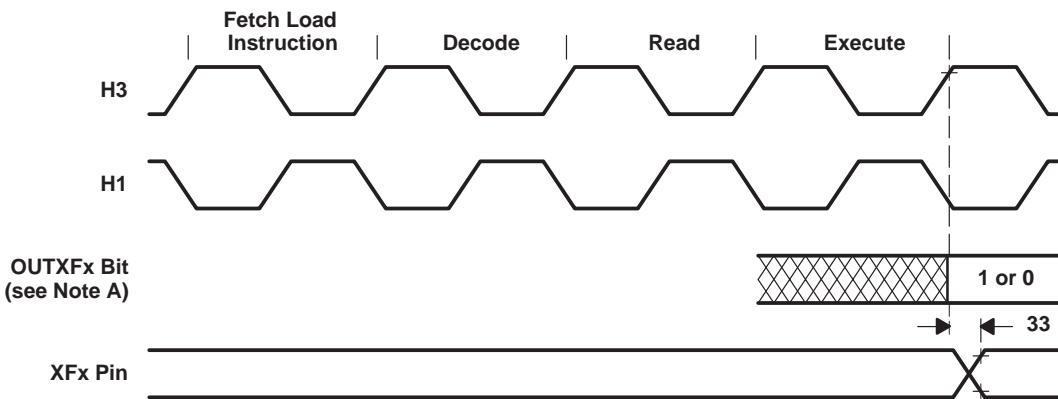
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loading when XF is configured as an output

The following table defines the timing parameter for loading the XF register when the XF_x pin is configured as an output.

timing for loading the XF register when configured as an output pin (see Figure 20)

| NO. | t _v (H3H-XF) Valid time, H3 high to XF _x | 'C31-40 'LC31-40 | | 'C31-50 | | 'C31-60 | | UNIT |
|-----|--|---------------------|-----|---------|-----|---------|-----|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | |
| 33 | t _v (H3H-XF) Valid time, H3 high to XF _x | 13 | | 12 | | 11 | | ns |



NOTE A: OUTXF_x represents either bit 2 or 6 of the IOF register.

Figure 20. Timing for Loading XF Register When Configured as an Output Pin

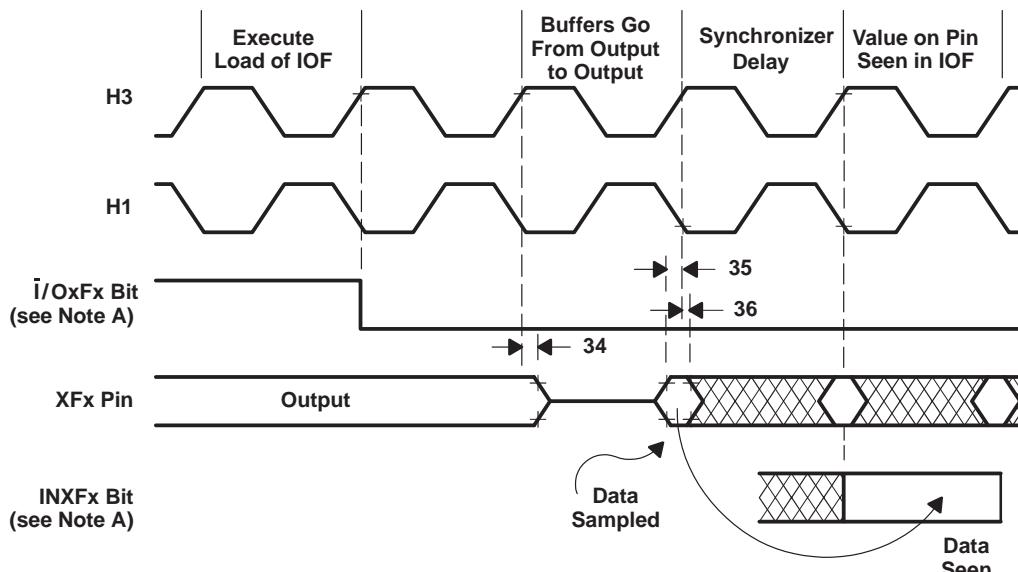
changing XF_x from an output to an input

The following table defines the timing parameters for changing the XF_x pin from an output pin to an input pin.

timing of XF_x changing from output to input mode for SMJ320C31 (see Figure 21)

| NO. | | 'C31-40 | | 'LC31-40 | | 'C31-50 | | 'C31-60 | | UNIT | |
|-----|--------------------------|---|-----|----------|-----|---------|-----|---------|-----|------|----|
| | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | | |
| 34 | t _h (H3H-XF) | Hold time, XF _x after H3 high | | 13* | | 13* | | 12* | | 11* | ns |
| 35 | t _{su} (XF-H1L) | Setup time, XF _x before H1 low | | 9 | | 10 | | 8 | | 8 | ns |
| 36 | t _h (H1L-XF) | Hold time, XF _x after H1 low | | 0 | | 0 | | 0 | | 0 | ns |

* This parameter is not production tested.



NOTE A: I/OXFx represents either bit 1 or bit 5 of the IOF register, and INXFx represents either bit 3 or bit 7 of the IOF register.

Figure 21. Timing for Change of XF_x From Output to Input Mode

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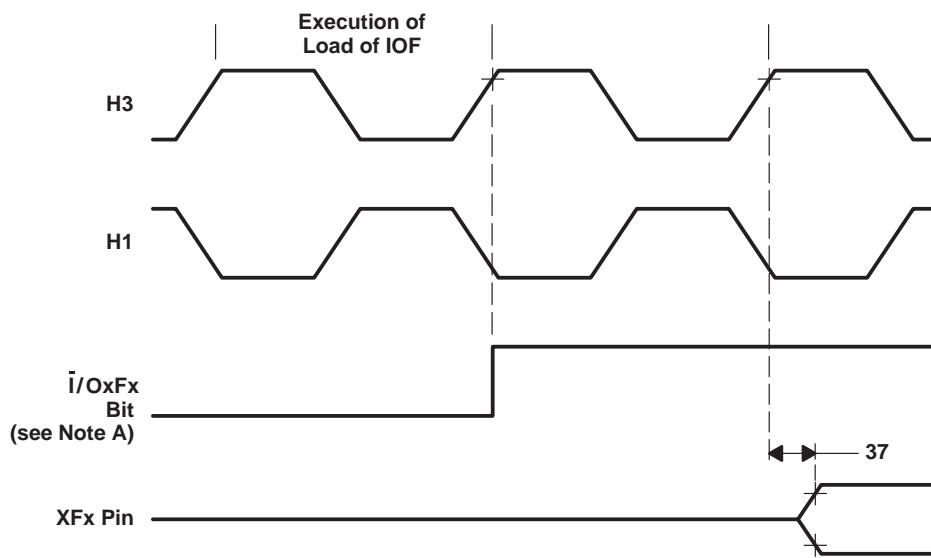
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changing XF_x from an input to an output

The following table defines the timing parameter for changing the XF_x pin from an input pin to an output pin.

timing for XF_x changing from input to output mode (see Figure 22)

| NO. | | 'C31-40 'LC31-40 | | 'C31-50 | | 'C31-60 | | UNIT |
|-----|---|---------------------|-----|---------|-----|---------|-----|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | |
| 37 | t _d (H3H-XFIO) Delay time, H3 high to XF _x switching from input to output | | | 17 | | 17 | 16 | ns |



NOTE A: I/OXF_x represents either bit 1 or bit 5 of the IOF register.

Figure 22. Timing for Change of XF_x From Input to Output Mode

reset timing

RESET is an asynchronous input that can be asserted at any time during a clock cycle. If the specified timings are met, the exact sequence shown in Figure 23 occurs; otherwise, an additional delay of one clock cycle is possible.

The asynchronous reset signals include XF0/1, CLKX0, DX0, FSX0, CLKR0, DR0, FSR0, and TCLK0/1.

Resetting the device initializes the primary- and expansion-bus control registers to seven software wait states and therefore results in slow external accesses until these registers are initialized.

HOLD is an asynchronous input and can be asserted during reset.

RESET timing (see Figure 23)

| NO. | | 'C31-40 | | 'LC31-40 | | 'C31-50 | | 'C31-60 | | UNIT | |
|-----|---------------------------------|--|-----|---------------|-----|---------------|-----|---------------|-----|---------------|----|
| | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | | |
| 38 | $t_{su}(\text{RESET-CIL})$ | Setup time, <u>RESET</u> before CLKIN low | 10 | $P \dagger^*$ | 10 | $P \dagger^*$ | 10 | $P \dagger^*$ | 7 | $P \dagger^*$ | ns |
| 39 | $t_d(\text{CLKINH-H1H})$ | Delay time, CLKIN high to H1 high (see Note 4) | 2 | 14 | 2 | 14 | 2 | 10 | 2 | 10 | ns |
| 40 | $t_d(\text{CLKINH-H1L})$ | Delay time, CLKIN high to H1 low (see Note 4) | 2 | 14 | 2 | 14 | 2 | 10 | 2 | 10 | ns |
| 41 | $t_{su}(\text{RESETH-H1L})$ | Setup time, <u>RESET</u> high before H1 low and after ten H1 clock cycles | 9 | | 9 | | 7 | | 6 | | ns |
| 42 | $t_d(\text{CLKINH-H3L})$ | Delay time, CLKIN high to H3 low (see Note 4) | 2 | 14 | 2 | 14 | 2 | 10 | 2 | 10 | ns |
| 43 | $t_d(\text{CLKINH-H3H})$ | Delay time, CLKIN high to H3 high (see Note 4) | 2 | 14 | 2 | 14 | 2 | 10 | 2 | 10 | ns |
| 44 | $t_{dis}(\text{H1H-DZ})$ | Disable time, H1 high to D (high impedance) | | 15* | | 13* | | 12* | | 11* | ns |
| 45 | $t_{dis}(\text{H3H-AZ})$ | Disable time, H3 high to A (high impedance) | | 9* | | 9* | | 8* | | 7* | ns |
| 46 | $t_d(\text{H3H-CONTROLH})$ | Delay time, H3 high to control signals high | | 9* | | 9* | | 8* | | 7* | ns |
| 47 | $t_d(\text{H1H-RWH})$ | Delay time, H1 high to R/W high | | 9* | | 9* | | 8* | | 7* | ns |
| 48 | $t_d(\text{H1H-IACKH})$ | Delay time, H1 high to IACK high | | 9* | | 9* | | 8* | | 7* | ns |
| 49 | $t_{dis}(\text{RESETL-ASYNCH})$ | Disable time, <u>RESET</u> low to asynchronous reset signals disabled (high impedance) | | 21* | | 21* | | 17* | | 14* | ns |

$\dagger P = t_c(CI)$

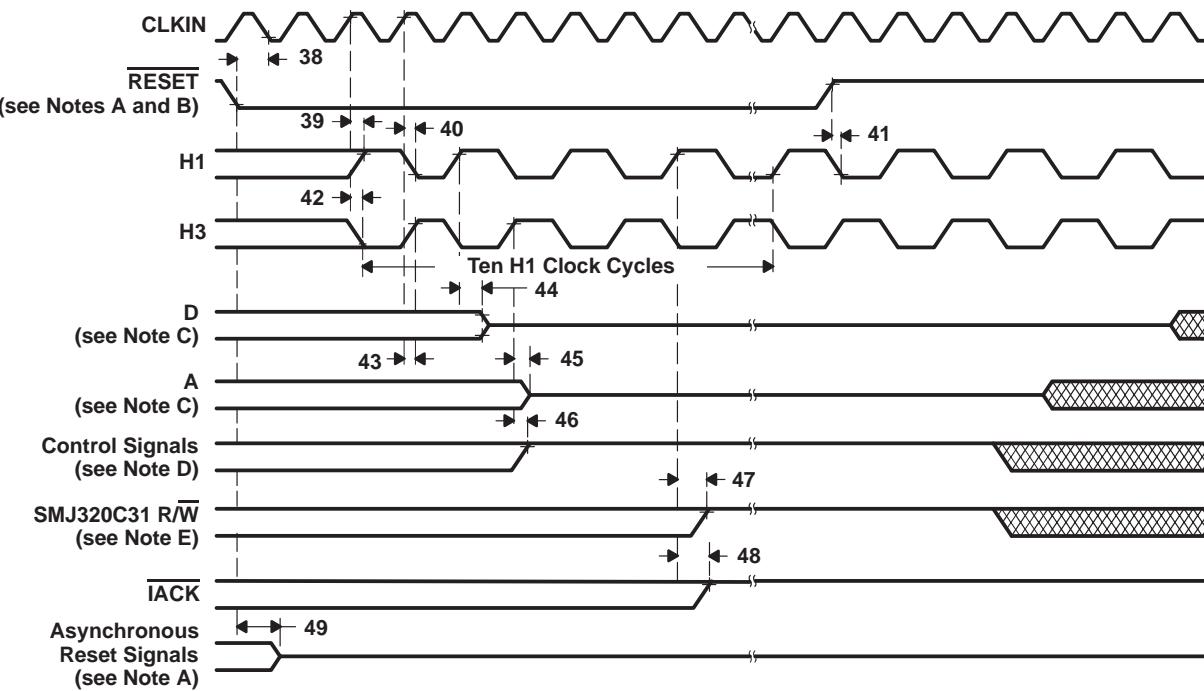
* This parameter is not production tested.

NOTE 4: See Figure 12 and Figure 13 for typical temperature dependence.

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RESET timing (continued)



NOTES:

- Asynchronous reset signals include XF0/1, CLKX0, DX0, FSX0, CLKR0, DR0, FSR0, and TCLK0/1.
- RESET is an asynchronous input and can be asserted at any point during a clock cycle. If the specified timings are met, the exact sequence shown occurs; otherwise, an additional delay of one clock cycle is possible.
- In microprocessor mode, the reset vector is fetched twice, with seven software wait states each time. In microcomputer mode, the reset vector is fetched twice, with no software wait states.
- Control signals include STRB.
- The R/W outputs are placed in a high-impedance state during reset and can be provided with a resistive pullup, nominally 18–22 kΩ, if undesirable spurious writes are caused when these outputs go low.

Figure 23. Timing for RESET

interrupt response timing

The following table defines the timing parameters for the $\overline{\text{INT}}$ signals.

timing for $\overline{\text{INT3}}-\overline{\text{INT0}}$ response (see Figure 24)

| NO. | | 'C31-40 | | 'LC31-40 | | 'C31-50 | | 'C31-60 | | UNIT |
|-----|--------------------------|---|-----|------------------|-----|------------------|-----|------------------|-----|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| 50 | $t_{su}(\text{INT-H1L})$ | Setup time, $\overline{\text{INT3}}-\overline{\text{INT0}}$ before H1 low | 13 | 15 | 11 | 8 | | | | ns |
| 51 | $t_w(\text{INT})$ | Pulse duration, interrupt to ensure only one interrupt | P | $2P^{\dagger}$ * | P | $2P^{\dagger}$ * | P | $2P^{\dagger}$ * | P | ns |

[†] $P = t_c(H)$

* This parameter is not production tested.

The interrupt ($\overline{\text{INT}}$) pins are asynchronous inputs that can be asserted at any time during a clock cycle. The SMJ320C3x interrupts are level-sensitive, not edge-sensitive. Interrupts are detected on the falling edge of H1. Therefore, interrupts must be set up and held to the falling edge of H1 for proper detection. The CPU and DMA respond to detected interrupts on instruction-fetch boundaries only.

For the processor to recognize only one interrupt on a given input, an interrupt pulse must be set up and held to:

- A minimum of one H1 falling edge
- No more than two H1 falling edges

The SMJ320C3x can accept an interrupt from the same source every two H1 clock cycles.

If the specified timings are met, the exact sequence shown in Figure 24 occurs; otherwise, an additional delay of one clock cycle is possible.

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timing parameters for INT3–INT0 response (continued)

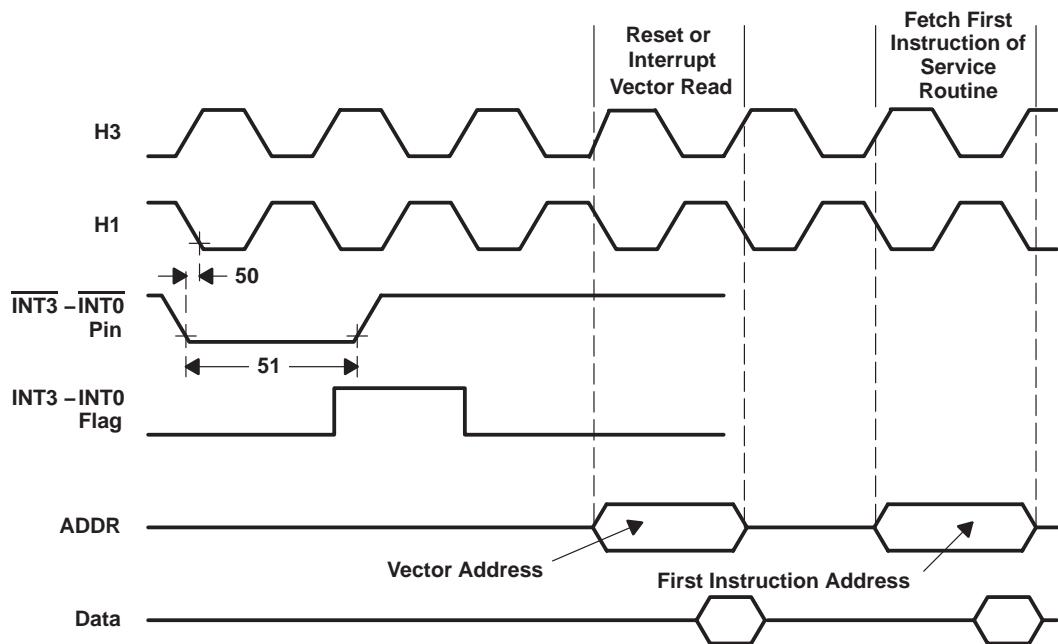


Figure 24. Timing for INT3–INT0 Response

interrupt-acknowledge timing

The IACK output goes active on the first half-cycle (H1 rising) of the decode phase of the IACK instruction and goes inactive at the first half-cycle (H1 rising) of the read phase of the IACK instruction.

timing for IACK (see Note 5 and Figure 25)

| NO. | | 'C31-40 'LC31-40 | | 'C31-50 | | 'C31-60 | | UNIT |
|-----|--------------------|---|-----|---------|-----|---------|-----|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | |
| 52 | $t_{d(H1H-IACKL)}$ | Delay time, H1 high to <u>IACK</u> low | | 9 | | 7 | | 6 ns |
| 53 | $t_{d(H1H-IACKH)}$ | Delay time, H1 high to <u>IACK</u> high | | 9 | | 7 | | 6 ns |

NOTE 5: IACK goes active on the first half-cycle (H1 rising) of the decode phase of the IACK instruction and goes inactive at the first half-cycle (H1 rising) of the read phase of the IACK instruction. Because of pipeline conflicts, IACK remains low for one cycle even if the decode phase of the IACK instruction is extended.

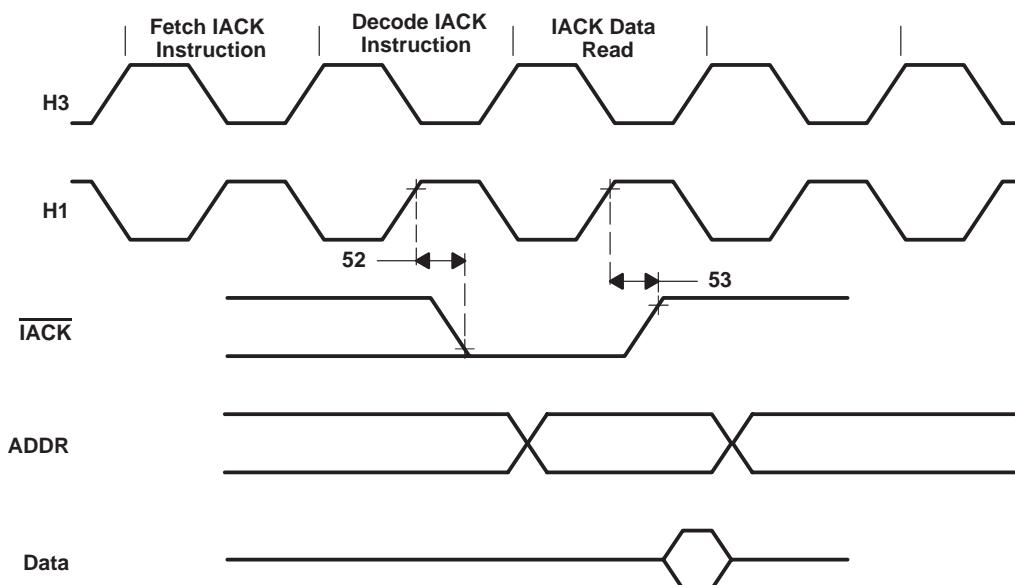


Figure 25. Timing for IACK

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serial-port timing for SMJ320C31-40 and SMJ320LC31-40 (see Figure 26 and Figure 27)

| NO. | | | 'C31-40 'LC31-40 | | UNIT |
|-----|---------------------|--|---------------------|--|--------|
| | | | MIN | MAX | |
| 54 | $t_d(H1H-SCK)$ | Delay time, H1 high to internal CLKX/R | | | 13 ns |
| 55 | $t_c(SCK)$ | Cycle time, CLKX/R | CLKX/R ext | $t_c(H) \times 2.6$ | ns |
| | | | CLKX/R int | $t_c(H) \times 2$ $t_c(H) \times 2^{32}$ | |
| 56 | $t_w(SCK)$ | Pulse duration, CLKX/R high/low | CLKX/R ext | $t_c(H) + 10$ | ns |
| | | | CLKX/R int | $[t_c(SCK)/2] - 5$ $[t_c(SCK)/2] + 5$ | |
| 57 | $t_r(SCK)$ | Rise time, CLKX/R | | | 7 ns |
| 58 | $t_f(SCK)$ | Fall time, CLKX/R | | | 7 ns |
| 59 | $t_d(C-DX)$ | Delay time, CLKX to DX valid | CLKX ext | 30 | ns |
| | | | CLKX int | 17 | |
| 60 | $t_{su}(DR-CLKRL)$ | Setup time, DR before CLKR low | CLKR ext | 9 | ns |
| | | | CLKR int | 21 | |
| 61 | $t_h(CLKRL-DR)$ | Hold time, DR from CLKR low | CLKR ext | 9 | ns |
| | | | CLKR int | 0 | |
| 62 | $t_d(C-FSX)$ | Delay time, CLKX to internal FSX high/low | CLKX ext | 27 | ns |
| | | | CLKX int | 15 | |
| 63 | $t_{su}(FSR-CLKRL)$ | Setup time, FSR before CLKR low | CLKR ext | 9 | ns |
| | | | CLKR int | 9 | |
| 64 | $t_h(SCKL-FS)$ | Hold time, FSX/R input from CLKX/R low | CLKX/R ext | 9 | ns |
| | | | CLKX/R int | 0 | |
| 65 | $t_{su}(FSX-C)$ | Setup time, external FSX before CLKX | CLKX ext | $-[t_c(H) - 8]^*$ $[t_c(SCK)/2] - 10^*$ | ns |
| | | | CLKX int | $[t_c(H) - 21]^*$ $t_c(SCK)/2^*$ | |
| 66 | $t_d(CH-DX)V$ | Delay time, CLKX to first DX bit, FSX precedes CLKX high | CLKX ext | 30* | ns |
| | | | CLKX int | 18* | |
| 67 | $t_d(FSX-DX)V$ | Delay time, FSX to first DX bit, CLKX precedes FSX | | | 30* ns |
| 68 | $t_d(CH-DXZ)$ | Delay time, CLKX high to DX high impedance following last data bit | | | 17* ns |

* This parameter is not production tested.

serial-port timing for SMJ320C31-50 (see Figure 26 and Figure 27)

| NO. | | 'C31-50 | | UNIT |
|-----|---------------------|--|---|------|
| | | MIN | MAX | |
| 54 | $t_d(H1H-SCK)$ | Delay time, H1 high to internal CLKX/R | 10 | ns |
| 55 | $t_c(SCK)$ | Cycle time, CLKX/R | CLKX/R ext $t_c(H) \times 2.6$ | ns |
| | | | CLKX/R int $t_c(H) \times 2$ $t_c(H) \times 2^{32}$ | |
| 56 | $t_w(SCK)$ | Pulse duration, CLKX/R high/low | CLKX/R ext $t_c(H) + 10$ | ns |
| | | | CLKX/R int $[t_c(SCK)/2] - 5$ $[t_c(SCK)/2] + 5$ | |
| 57 | $t_r(SCK)$ | Rise time, CLKX/R | 6 | ns |
| 58 | $t_f(SCK)$ | Fall time, CLKX/R | 6 | ns |
| 59 | $t_d(C-DX)$ | Delay time, CLKX to DX valid | CLKX ext 24 | ns |
| | | | CLKX int 16 | |
| 60 | $t_{su}(DR-CLKRL)$ | Setup time, DR before CLKRL low | CLKR ext 9 | ns |
| | | | CLKR int 17 | |
| 61 | $t_h(CLKRL-DR)$ | Hold time, DR from CLKRL low | CLKR ext 7 | ns |
| | | | CLKR int 0 | |
| 62 | $t_d(C-FSX)$ | Delay time, CLKX to internal FSX high/low | CLKX ext 22 | ns |
| | | | CLKX int 15 | |
| 63 | $t_{su}(FSR-CLKRL)$ | Setup time, FSR before CLKRL low | CLKR ext 7 | ns |
| | | | CLKR int 7 | |
| 64 | $t_h(SCKL-FS)$ | Hold time, FSX/R input from CLKX/R low | CLKX/R ext 7 | ns |
| | | | CLKX/R int 0 | |
| 65 | $t_{su}(FSX-C)$ | Setup time, external FSX before CLKX | CLKX ext $-[t_c(H) - 8]^*$ $[t_c(SCK)/2] - 10^*$ | ns |
| | | | CLKX int $-[t_c(H) - 21]^*$ $t_c(SCK)/2^*$ | |
| 66 | $t_d(CH-DX)V$ | Delay time, CLKX to first DX bit, FSX precedes CLKX high | CLKX ext 24* | ns |
| | | | CLKX int 14* | |
| 67 | $t_d(FSX-DX)V$ | Delay time, FSX to first DX bit, CLKX precedes FSX | 24* | ns |
| 68 | $t_d(CH-DXZ)$ | Delay time, CLKX high to DX high impedance following last data bit | 14* | ns |

* This parameter is not production tested.

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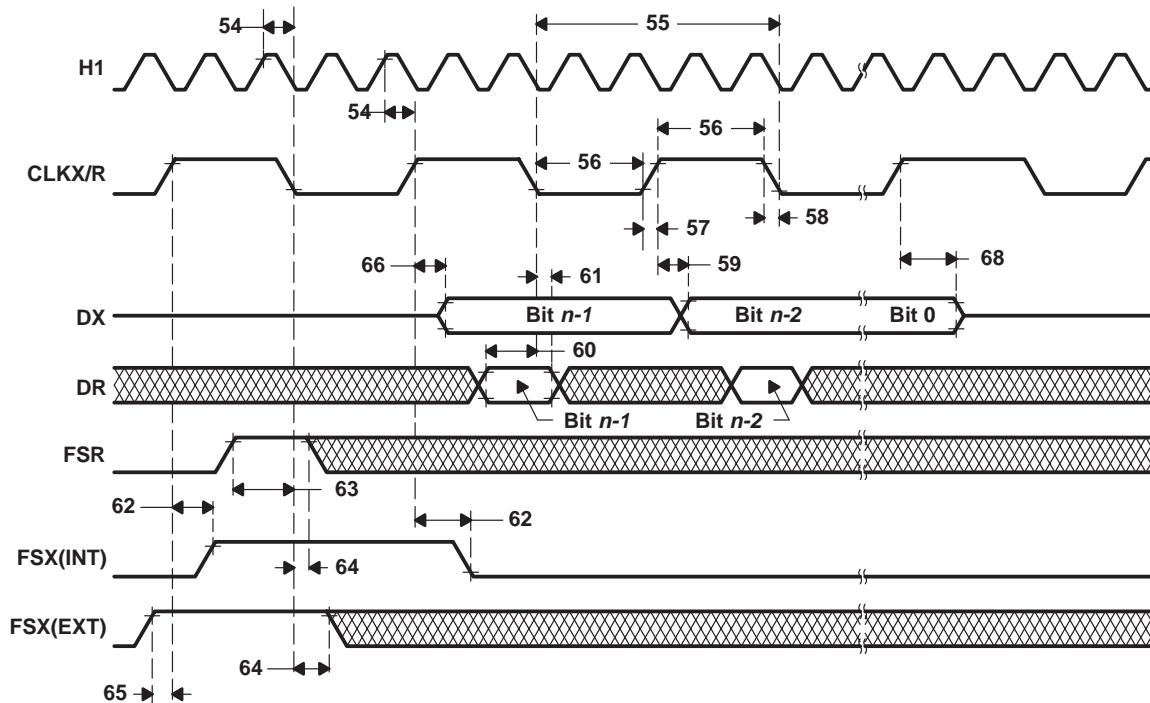
serial-port timing for SMJ320C31-60 (see Figure 26 and Figure 27)

| NO. | | | 'C31-60 | | UNIT |
|-----|---------------------|--|------------|--|------|
| | | | MIN | MAX | |
| 54 | $t_d(H1H-SCK)$ | Delay time, H1 high to internal CLKX/R | 8 | | ns |
| 55 | $t_c(SCK)$ | Cycle time, CLKX/R | CLKX/R ext | $t_c(H) \times 2.6$ | ns |
| | | | CLKX/R int | $t_c(H) \times 2$ $t_c(H) \times 2^{32}$ | |
| 56 | $t_w(SCK)$ | Pulse duration, CLKX/R high/low | CLKX/R ext | $t_c(H) + 10$ | ns |
| | | | CLKX/R int | $[t_c(SCK)/2] - 5$ $[t_c(SCK)/2] + 5$ | |
| 57 | $t_r(SCK)$ | Rise time, CLKX/R | 5 | | ns |
| 58 | $t_f(SCK)$ | Fall time, CLKX/R | 5 | | ns |
| 59 | $t_d(C-DX)$ | Delay time, CLKX to DX valid | CLKX ext | 20 | ns |
| | | | CLKX int | 15 | |
| 60 | $t_{su}(DR-CLKRL)$ | Setup time, DR before CLKRL low | CLKR ext | 8 | ns |
| | | | CLKR int | 15 | |
| 61 | $t_h(CLKRL-DR)$ | Hold time, DR from CLKRL low | CLKR ext | 6 | ns |
| | | | CLKR int | 0 | |
| 62 | $t_d(C-FSX)$ | Delay time, CLKX to internal FSX high/low | CLKX ext | 20 | ns |
| | | | CLKX int | 14 | |
| 63 | $t_{su}(FSR-CLKRL)$ | Setup time, FSR before CLKRL low | CLKR ext | 6 | ns |
| | | | CLKR int | 6 | |
| 64 | $t_h(SCKL-FS)$ | Hold time, FSX/R input from CLKX/R low | CLKX/R ext | 6 | ns |
| | | | CLKX/R int | 0 | |
| 65 | $t_{su}(FSX-C)$ | Setup time, external FSX before CLKX | CLKX ext | $-[t_c(H) - 8]^*$ $[t_c(SCK)/2] - 10^*$ | ns |
| | | | CLKX int | $-[t_c(H) - 21]^*$ $t_c(SCK)/2^*$ | |
| 66 | $t_d(CH-DX)V$ | Delay time, CLKX to first DX bit, FSX precedes CLKX high | CLKX ext | 20* | ns |
| | | | CLKX int | 12* | |
| 67 | $t_d(FSX-DX)V$ | Delay time, FSX to first DX bit, CLKX precedes FSX | 20* | | ns |
| 68 | $t_d(CH-DXZ)$ | Delay time, CLKX high to DX high impedance following last data bit | 12* | | ns |

* This parameter is not production tested.

data-rate timing modes

Unless otherwise indicated, the data-rate timings shown in Figure 26 and Figure 27 are valid for all serial-port modes, including handshake. For a functional description of serial-port operation, see subsection 8.2.12 of the *TMS320C3x User's Guide* (literature number SPRU031).



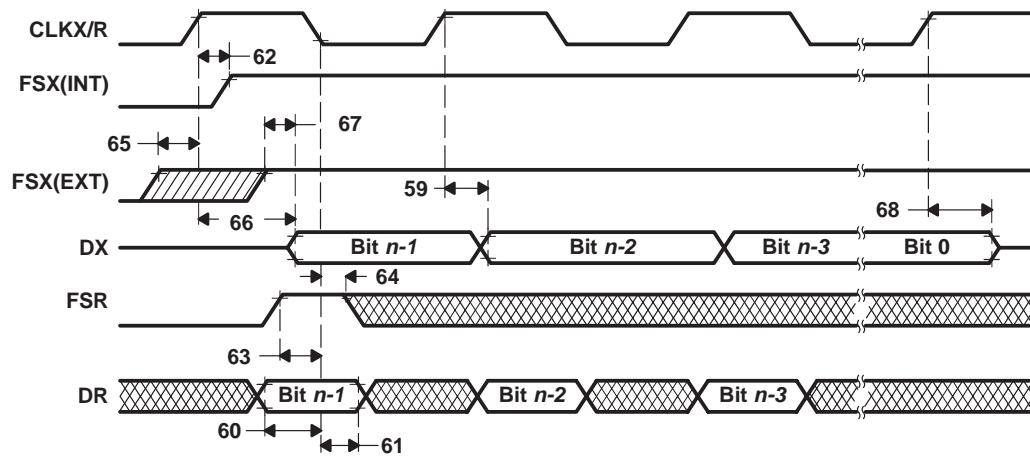
NOTES: A. Timing diagrams show operations with CLKXP = CLKRP = FSXP = FSRP = 0.
B. Timing diagrams depend on the length of the serial-port word, where n = 8, 16, 24, or 32 bits, respectively.

Figure 26. Timing for Fixed Data-Rate Mode

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data-rate timing modes (continued)



NOTES:

- Timing diagrams show operation with $\text{CLKXP} = \text{CLKRP} = \text{FSXP} = \text{FSRP} = 0$.
- Timing diagrams depend on the length of the serial-port word, where $n = 8, 16, 24$, or 32 bits, respectively.
- The timings that are not specified expressly for the variable data-rate mode are the same as those that are specified for the fixed data-rate mode.

Figure 27. Timing for Variable Data-Rate Mode

HOLD timing

HOLD is an asynchronous input that can be asserted at any time during a clock cycle. If the specified timings are met, the exact sequence shown in Figure 27 occurs; otherwise, an additional delay of one clock cycle is possible.

The NOHOLD bit of the primary-bus control register overrides the **HOLD** signal. When this bit is set, the device comes out of hold and prevents future hold cycles.

Asserting **HOLD** prevents the processor from accessing the primary bus. Program execution continues until a read from or a write to the primary bus is requested. In certain circumstances, the first write is pending, thus allowing the processor to continue until a second write is encountered.

timing for HOLD/HOLDA (see Figure 28)

| NO. | | 'C31-40 | | 'LC31-40 | | 'C31-50 | | 'C31-60 | | UNIT |
|-----|----------------------------------|---|--------------|----------|--------------|---------|--------------|---------|--------------|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| 69 | $t_{su}(\text{HOLD}-\text{H1L})$ | Setup time, HOLD before H1 low | 13 | 13 | | 10 | | 8 | | ns |
| 70 | $t_v(\text{H1L}-\text{HOLDA})$ | Valid time, HOLDA after H1 low | 0† | 9 | 0* | 9 | 0* | 7 | 0* | 6 |
| 71 | $t_w(\text{HOLD})^\dagger$ | Pulse duration, HOLD low | $2t_c(H)$ | | $2t_c(H)$ | | $2t_c(H)$ | | $2t_c(H)$ | ns |
| 72 | $t_w(\text{HOLDA})$ | Pulse duration, HOLDA low | $t_{cH}-5^*$ | | $t_{cH}-5^*$ | | $t_{cH}-5^*$ | | $t_{cH}-5^*$ | ns |
| 73 | $t_d(\text{H1L}-\text{SH})H$ | Delay time, H1 low to STRB high for a HOLD | 0* | 9 | 0* | 9 | 0* | 7 | 0* | 6 |
| 74 | $t_{dis}(\text{H1L}-\text{S})$ | Disable time, H1 low to STRB to the high-impedance state | 0* | 9* | 0* | 9* | 0* | 7* | 0* | 7* |
| 75 | $t_{en}(\text{H1L}-\text{S})$ | Enable time, H1 low to STRB enabled (active) | 0* | 9 | 0* | 9 | 0* | 7 | 0* | 6 |
| 76 | $t_{dis}(\text{H1L}-\text{RW})$ | Disable time, H1 low to R/W to the high-impedance state | 0* | 9* | 0* | 9* | 0* | 8* | 0* | 7* |
| 77 | $t_{en}(\text{H1L}-\text{RW})$ | Enable time, H1 low to R/W enabled (active) | 0* | 9 | 0* | 9 | 0* | 7 | 0* | 6 |
| 78 | $t_{dis}(\text{H1L}-\text{A})$ | Disable time, H1 low to address to the high-impedance state | 0* | 9* | 0* | 10* | 0* | 8* | 0* | 7* |
| 79 | $t_{en}(\text{H1L}-\text{A})$ | Enable time, H1 low to address enabled (valid) | 0* | 13 | 0* | 13 | 0* | 10 | 0* | 11? |
| 80 | $t_{dis}(\text{H1H}-\text{D})$ | Disable time, H1 high to data to the high-impedance state | 0* | 12* | 0* | 9* | 0* | 10* | 0* | 7* |

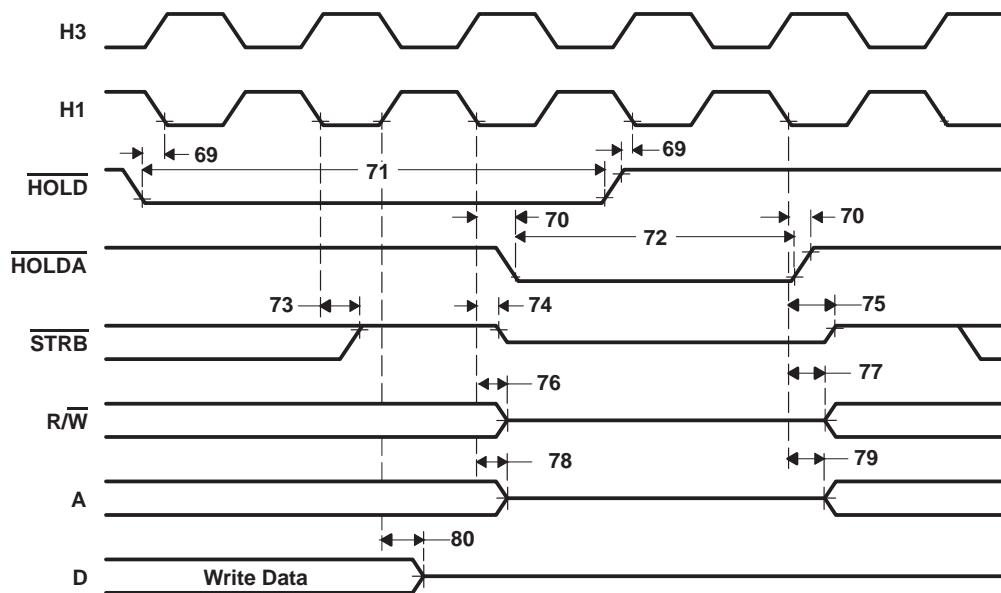
† **HOLD** is an asynchronous input and can be asserted at any point during a clock cycle. If the specified timings are met, the exact sequence shown in Figure 28 occurs; otherwise, an additional delay of one clock cycle is possible.

* This parameter is not production tested.

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HOLD timing (continued)



NOTE A: HOLDA goes low in response to HOLD going low and continues to remain low until one H1 cycle after HOLD goes back high.

Figure 28. Timing for HOLD/HOLDA

general-purpose I/O timing

Peripheral pins include CLKX0, CLKR0, DX0, DR0, FSX0, FSR0, and TCLK0/1. The contents of the internal control registers associated with each peripheral define the modes for these pins.

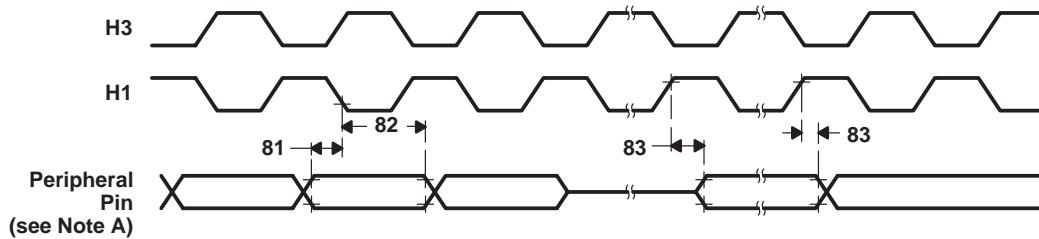
peripheral pin I/O timing

The table, timing parameters for peripheral pin general-purpose I/O, defines peripheral pin general-purpose I/O timing parameters.

timing requirements for peripheral pin general-purpose I/O (see Note 6 and Figure 29)

| NO. | | 'C31-33 | | 'C31-40 'LC31-40 | | 'C31-50 | | 'C31-60 | | UNIT |
|-----|---------------------------|--|-----|---------------------|-----|---------|-----|---------|-----|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| 81 | $t_{su}(\text{GPIO-H1L})$ | Setup time, general-purpose input before H1 low | 12 | 10 | | 9 | | 8 | | ns |
| 82 | $t_h(\text{H1L-GPIO})$ | Hold time, general-purpose input after H1 low | 0 | 0 | | 0 | | 0 | | ns |
| 83 | $t_d(\text{H1H-GPIO})$ | Delay time, general-purpose output after H1 high | | 15 | 13 | | 10 | | 8 | ns |

NOTE 6: Peripheral pins include CLKX0, CLKR0, DX0, DR0, FSX0, FSR0, and TCLK0/1. The modes of these pins are defined by the contents of internal-control registers associated with each peripheral.



NOTE A: Peripheral pins include CLKX0, CLKR0, DX0, DR0, FSX0, FSR0, and TCLK0/1.

Figure 29. Timing for Peripheral Pin General-Purpose I/O

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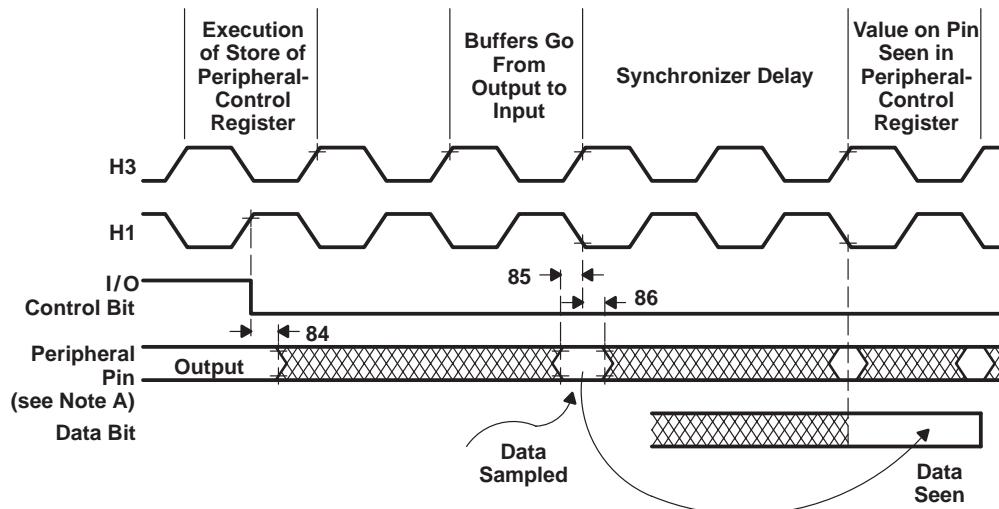
changing the peripheral pin I/O modes

The following tables show the timing parameters for changing the peripheral pin from a general-purpose output pin to a general-purpose input pin and vice versa.

timing requirements for peripheral pin changing from general-purpose output to input mode (see Note 6 and Figure 30)

| NO. | | 'C31-40 'LC31-40 | | 'C31-50 | | 'C31-60 | | UNIT |
|-----|--|---------------------|-----|---------|-----|---------|-----|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | |
| 84 | $t_{h(H1H)}$ Hold time, peripheral pin after H1 high | | | 13 | | 10 | | 8 ns |
| 85 | $t_{su(GPIO-H1L)}$ Setup time, peripheral pin before H1 low | | | 9 | | 9 | | 8 ns |
| 86 | $t_{h(H1L-GPIO)}$ Hold time, peripheral pin after H1 low | | | 0 | | 0 | | ns |

NOTE 6: Peripheral pins include CLKX0, CLKR0, DX0, DR0, FSX0, FSR0, and TCLK0/1. The modes of these pins are defined by the contents of internal-control registers associated with each peripheral.



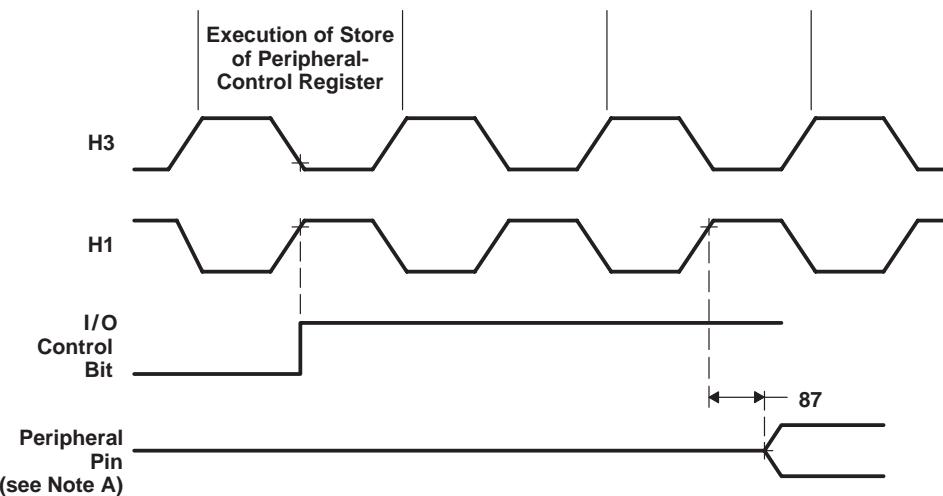
NOTE A: Peripheral pins include CLKX0, CLKR0, DX0, DR0, FSX0, FSR0, and TCLK0/1.

Figure 30. Timing for Change of Peripheral Pin From General-Purpose Output to Input Mode

timing for peripheral pin changing from general-purpose input to output mode (see Note 6 and Figure 31)

| NO. | | 'C31-40 'LC31-40 | | 'C31-50 | | 'C31-60 | | UNIT |
|-----|-----------------|--|-----|---------|-----|---------|-----|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | |
| 87 | $t_d(H1H-GPIO)$ | Delay time, H1 high to peripheral pin switching from input to output | | 13 | | 10 | 8 | ns |

NOTE 6: Peripheral pins include CLKX0, CLKR0, DX0, DR0, FSX0, FSR0, and TCLK0/1. The modes of these pins are defined by the contents of internal-control registers associated with each peripheral.



NOTE A: Peripheral pins include CLKX0, CLKR0, DX0, DR0, FSX0, FSR0, and TCLK0/1.

Figure 31. Timing for Change of Peripheral Pin From General-Purpose Input to Output Mode

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timer pin timing

Valid logic-level periods and polarity are specified by the contents of the internal control registers.

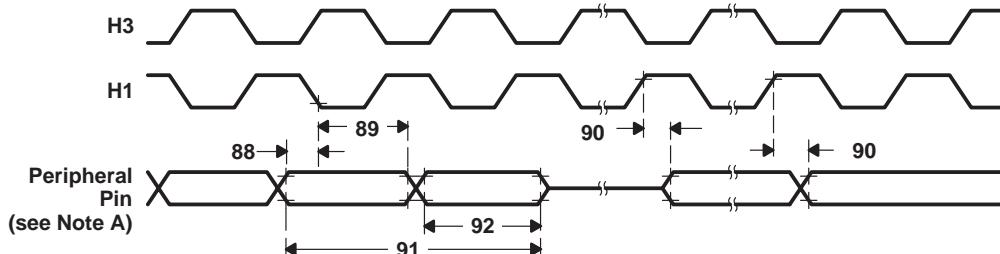
The following tables define the timing requirements for the timer pin.

timing for timer pin (see Figure 32 and Note 7)

| NO. | | 'C31-40, 'LC31-40 'C31-50 | | 'C31-60 | | UNIT |
|-----|--------------------|--|--|--|--|------|
| | | MIN | MAX | MIN | MAX | |
| 88 | $t_{su}(TCLK-H1L)$ | Setup time, TCLK external before H1 low | 10 | | 6 | ns |
| 89 | $t_h(H1L-TCLK)$ | Hold time, TCLK external after H1 low | 0 | | 0 | ns |
| 90 | $t_d(H1H-TCLK)$ | Delay time, H1 high to TCLK internal valid | | 9 | 8 | ns |
| 91 | $t_c(TCLK)$ | Cycle time, TCLK | $t_c(H) \times 2.6$ $t_c(H) \times 2$ | $t_c(H) \times 2.6$ $t_c(H) \times 2$ | $t_c(H) \times 2^{32*}$ | ns |
| 92 | $t_w(TCLK)$ | Pulse duration, TCLK high/low | $t_c(H) + 10$ $[t_c(TCLK)/2] - 5$ | $t_c(H) + 10$ $[t_c(TCLK)/2] - 5$ | $[t_c(TCLK)/2] + 5$ $[t_c(TCLK)/2] + 5$ | ns |

NOTE 7: Numbers 88 and 89 are applicable for a synchronous input clock. Timing parameters 91 and 92 are applicable for an asynchronous input clock.

* This parameter is not production tested.



NOTE A: HOLDA goes low in response to HOLD going low and continues to remain low until one H1 cycle after HOLD goes back high.

Figure 32. Timing for Timer Pin

SHZ pin timing

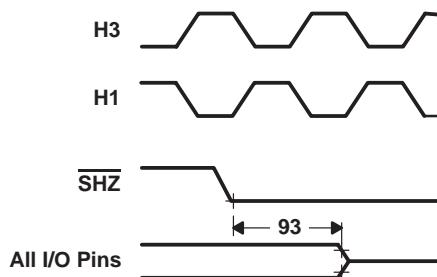
The following table defines the timing parameter for the SHZ pin.

timing parameters for SHZ (see Figure 33)

| NO. | | 'C31 'LC31 | | UNIT |
|-----|----------------|---|-----|-----------------|
| | | MIN | MAX | |
| 93 | $t_{dis}(SHZ)$ | Disable time, <u>SHZ</u> low to all O, I/O pins disabled (high impedance) | 0* | $2P^{\dagger*}$ |

$\dagger P = t_c(CI)$

* This parameter is not production tested.



NOTE A: Enabling SHZ destroys SMJ320C3x register and memory contents.
Assert SHZ = 1 and reset the SMJ320C3x to restore it to a known condition.

Figure 33. Timing for SHZ

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part order information

| DEVICE | TECHNOLOGY | POWER SUPPLY | OPERATING FREQUENCY | PACKAGE TYPE | PROCESSING LEVEL |
|-------------------|--------------------|----------------|---------------------|---|------------------|
| 5962-9205803MXA | 0.6- μ m CMOS | 5 V \pm 5% | 40 MHz | Ceramic 141-pin staggered PGA | DSCC SMD |
| SMJ320C31GFAM40 | 0.6- μ m CMOS | 5 V \pm 5% | 40 MHz | Ceramic 141-pin staggered PGA | QML |
| SM320C31GFAM40 | 0.6- μ m CMOS | 5 V \pm 5% | 40 MHz | Ceramic 141-pin staggered PGA | Std |
| 5962-9205803MYA | 0.6- μ m CMOS | 5 V \pm 5% | 40 MHz | Ceramic 132-pin quad flatpack with nonconductive tie bar. | DSCC SMD |
| SMJ320C31HFGM40 | 0.6- μ m CMOS | 5 V \pm 5% | 40 MHz | Ceramic 132-lead quad flatpack with a nonconductive tie bar | QML |
| SM320C31HFGM40 | 0.6- μ m CMOS | 5 V \pm 5% | 40 MHz | Ceramic 132-lead quad flatpack with a nonconductive tie bar | Std |
| 5962-9205803Q9A | 0.72- μ m CMOS | 5 V \pm 5% | 40 MHz | C31-40 KGD (known good die) | DSCC SMD |
| SMJ320C31KGDM40B | 0.72- μ m CMOS | 5 V \pm 5% | 40 MHz | C31-40 KGD (known good die) | QML |
| 5962-9205804MXA | 0.6- μ m CMOS | 5 V \pm 5% | 50 MHz | Ceramic 141-pin staggered PGA | DSCC SMD |
| SMJ320C31GFAM50 | 0.6- μ m CMOS | 5 V \pm 5% | 50 MHz | Ceramic 141-pin staggered PGA | QML |
| SM320C31GFAM50 | 0.6- μ m CMOS | 5 V \pm 5% | 50 MHz | Ceramic 141-pin staggered PGA | Std |
| 5962-9205804MYA | 0.6- μ m CMOS | 5 V \pm 5% | 50 MHz | Ceramic 132-pin quad flatpack with nonconductive tie bar. | DSCC SMD |
| SMJ320C31HFGM50 | 0.6- μ m CMOS | 5 V \pm 5% | 50 MHz | Ceramic 132-lead quad flatpack with nonconductive tie bar | QML |
| SM320C31HFGM50 | 0.6- μ m CMOS | 5 V \pm 5% | 50 MHz | Ceramic 132-lead quad flatpack with nonconductive tie bar | Std |
| 5962-9205805QXA | 0.6- μ m CMOS | 5 V \pm 5% | 60 MHz | Ceramic 141-pin staggered PGA | DSCC SMD |
| SMJ320C31GFAS60 | 0.6- μ m CMOS | 5 V \pm 5% | 60 MHz | Ceramic 141-pin staggered PGA | QML |
| SM320C31GFAS60 | 0.6- μ m CMOS | 5 V \pm 5% | 60 MHz | Ceramic 141-pin staggered PGA | Std |
| 5962-9205805QYA | 0.6- μ m CMOS | 5 V \pm 5% | 60 MHz | Ceramic 132-pin quad flatpack with nonconductive tie bar. | DSCC SMD |
| SMJ320C31HFGS60 | 0.6- μ m CMOS | 5 V \pm 5% | 60 MHz | Ceramic 132-lead quad flatpack with nonconductive tie bar | QML |
| SM320C31HFGS60 | 0.6- μ m CMOS | 5 V \pm 5% | 60 MHz | Ceramic 132-lead quad flatpack with nonconductive tie bar | Std |
| 5962-9760601NXB | 0.72- μ m CMOS | 3.3 V \pm 5% | 40 MHz | Plastic 132-lead good flatpack | DSCC SMD |
| SMQ320LC31PQM40 | 0.72- μ m CMOS | 3.3 V \pm 5% | 40 MHz | Plastic 132-lead good flatpack | QML |
| 5962-9760601Q9A | 0.72- μ m CMOS | 3.3 V \pm 5% | 40 MHz | LC31-40 KGD (known good die) | DSCC SMD |
| SMJ320LC31KGDM40B | 0.72- μ m CMOS | 3.3 V \pm 5% | 40 MHz | LC31-40 KGD (known good die) | QML |

part order information (continued)

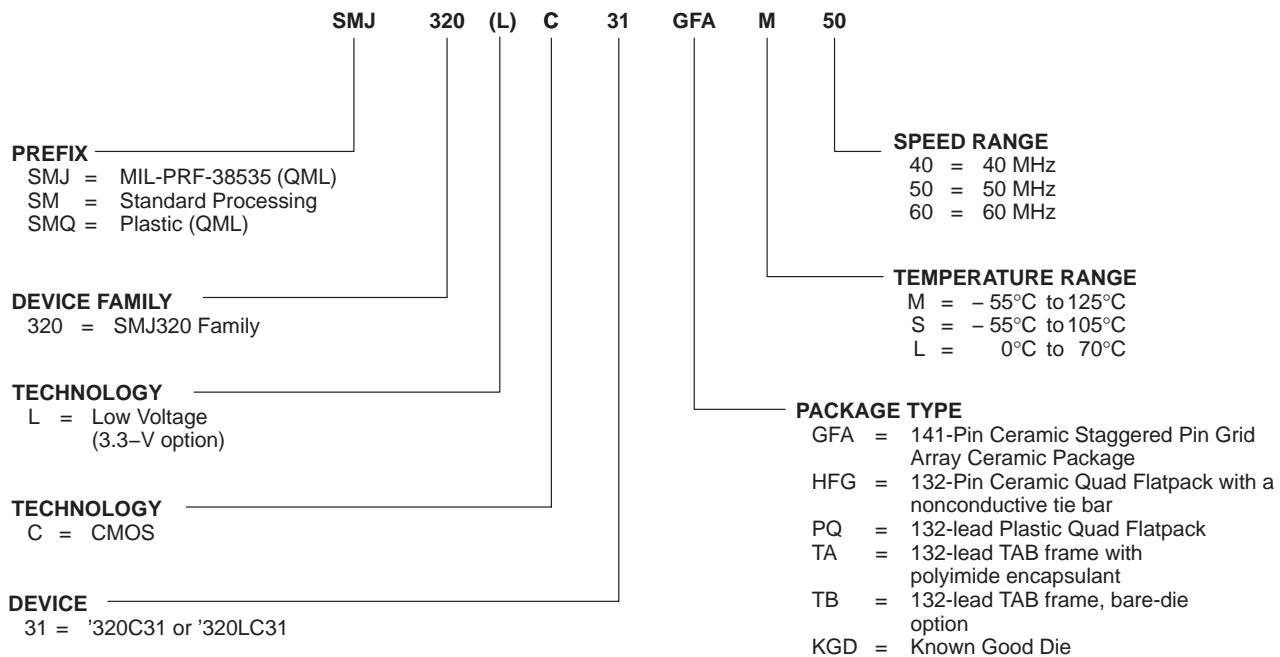


Figure 34. Device Nomenclature

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| 5962-9205803MXA | ACTIVE | CPGA | GFA | 141 | 1 | TBD | Call TI | N / A for Pkg Type |
| 5962-9205803M XC | ACTIVE | CPGA | GFA | 141 | 1 | TBD | Call TI | N / A for Pkg Type |
| 5962-9205803MYA | ACTIVE | CFP | HFG | 132 | 1 | TBD | Call TI | N / A for Pkg Type |
| 5962-9205804MXA | ACTIVE | CPGA | GFA | 141 | 1 | TBD | Call TI | N / A for Pkg Type |
| 5962-9205804M XC | ACTIVE | CPGA | GFA | 141 | 1 | TBD | Call TI | N / A for Pkg Type |
| 5962-9205804MYA | ACTIVE | CFP | HFG | 132 | 1 | TBD | Call TI | N / A for Pkg Type |
| 5962-9205805QXA | ACTIVE | CPGA | GFA | 141 | 1 | TBD | Call TI | N / A for Pkg Type |
| 5962-9205805Q YA | ACTIVE | CFP | HFG | 132 | 1 | TBD | Call TI | N / A for Pkg Type |
| 5962-9760601NXB | ACTIVE | BQFP | PQ | 132 | 1 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-4-260C-72 HR |
| 5962-9760601Q9A | OBsolete | XCEPT | KGD | 0 | | TBD | Call TI | Call TI |
| SM320C31GFAM50 | ACTIVE | CPGA | GFA | 141 | 1 | TBD | Call TI | N / A for Pkg Type |
| SM320C31GFAS60 | ACTIVE | CPGA | GFA | 141 | 1 | TBD | Call TI | N / A for Pkg Type |
| SM320C31HFGM40 | ACTIVE | CFP | HFG | 132 | 1 | TBD | Call TI | N / A for Pkg Type |
| SM320C31HFGM50 | ACTIVE | CFP | HFG | 132 | 1 | TBD | Call TI | N / A for Pkg Type |
| SMJ320C31GFAM40 | ACTIVE | CPGA | GFA | 141 | 1 | TBD | Call TI | N / A for Pkg Type |
| SMJ320C31GFAM50 | ACTIVE | CPGA | GFA | 141 | 1 | TBD | Call TI | N / A for Pkg Type |
| SMJ320C31GFAS60 | ACTIVE | CPGA | GFA | 141 | 1 | TBD | Call TI | N / A for Pkg Type |
| SMJ320C31HFGM40 | ACTIVE | CFP | HFG | 132 | 1 | TBD | Call TI | N / A for Pkg Type |
| SMJ320C31HFGM50 | ACTIVE | CFP | HFG | 132 | 1 | TBD | Call TI | N / A for Pkg Type |
| SMJ320C31HF GS60 | ACTIVE | CFP | HFG | 132 | 1 | TBD | Call TI | N / A for Pkg Type |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SM320C31, SMJ320C31 :

- Catalog: [TMS320C31](#)

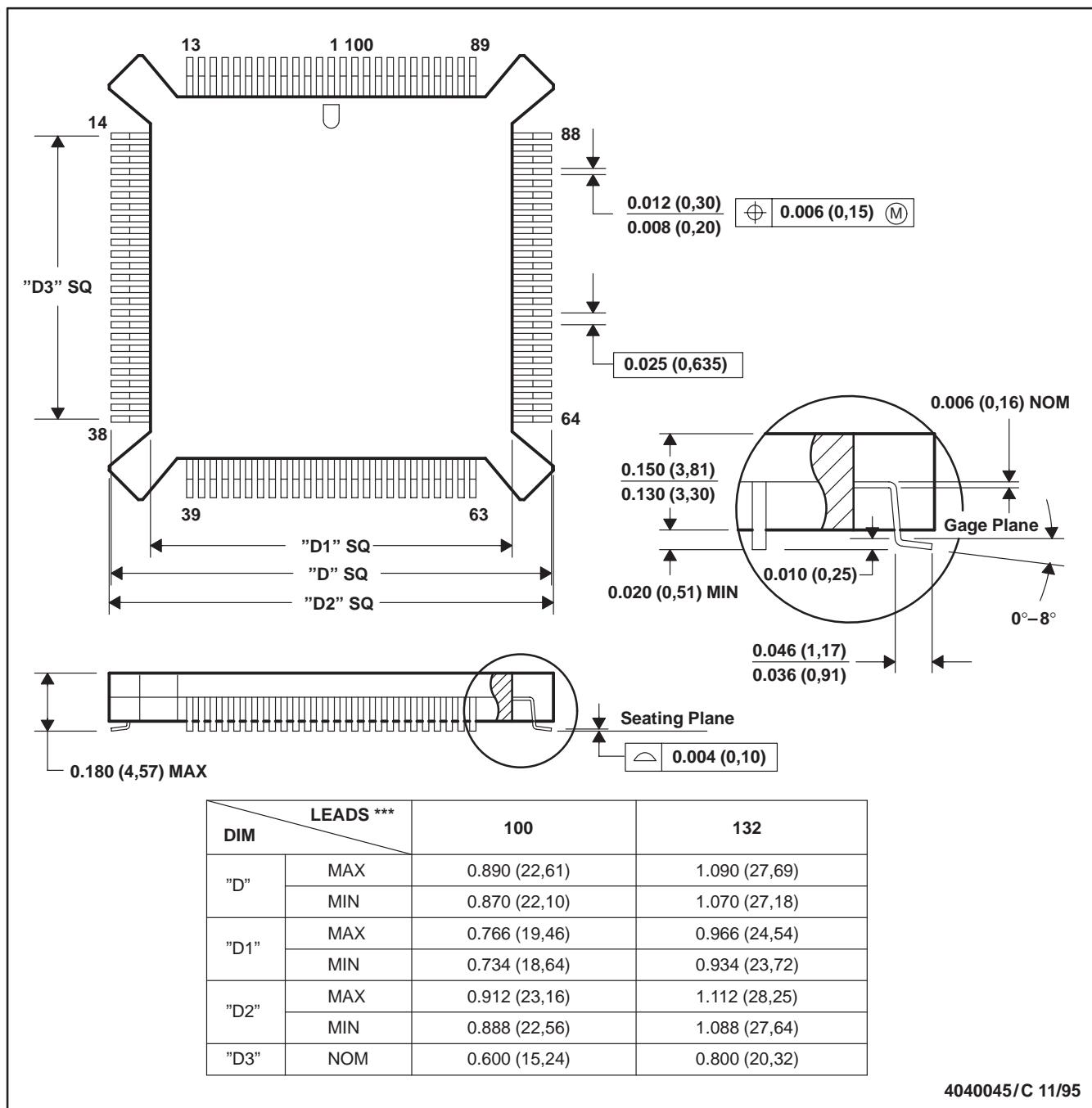
NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

PQ (S-PQFP-G***)

PLASTIC QUAD FLATPACK

100 LEAD SHOWN

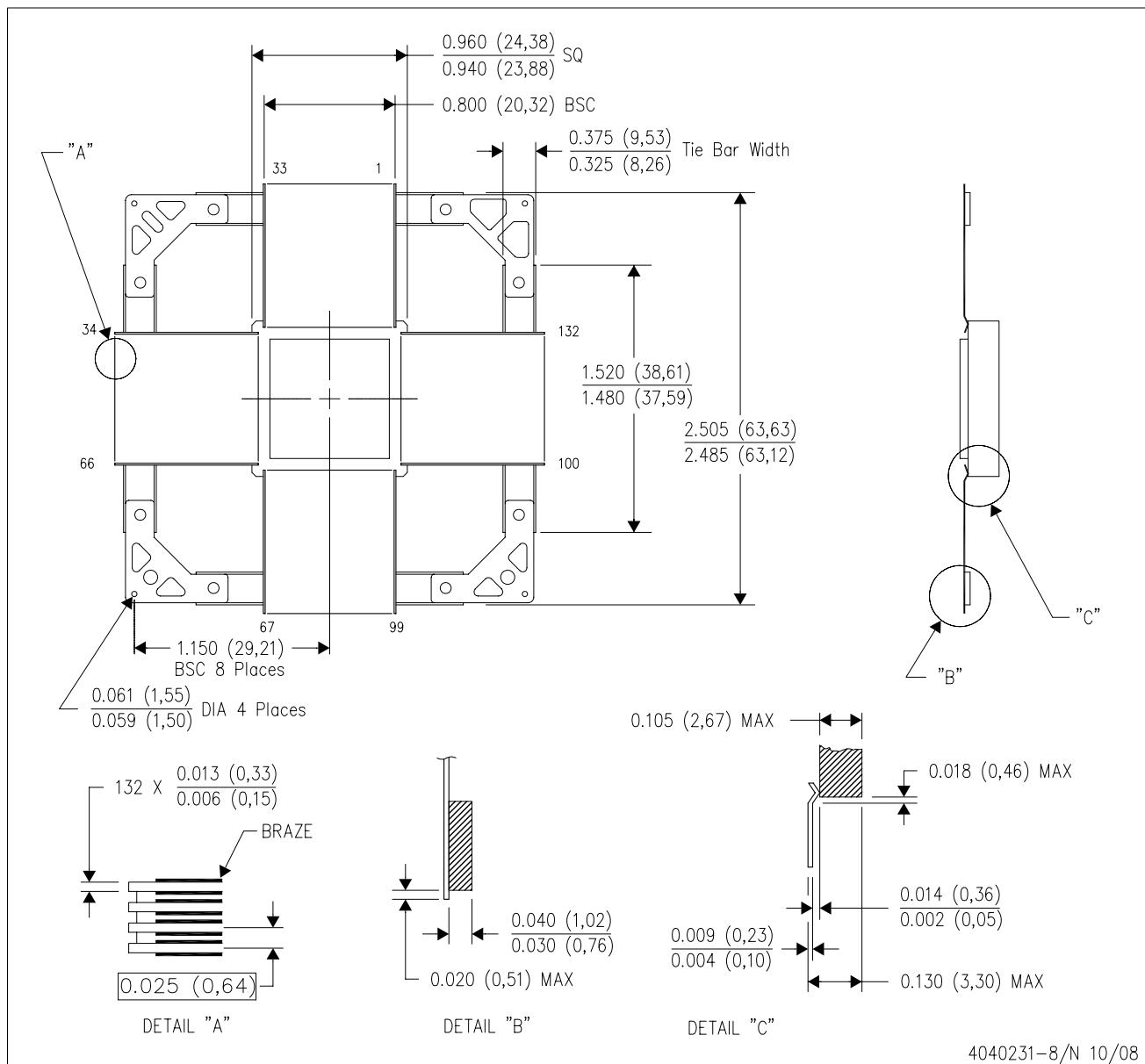


4040045/C 11/95

NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MO-069

HFG (S-CQFP-F132)

CERAMIC QUAD FLATPACK WITH NCTB

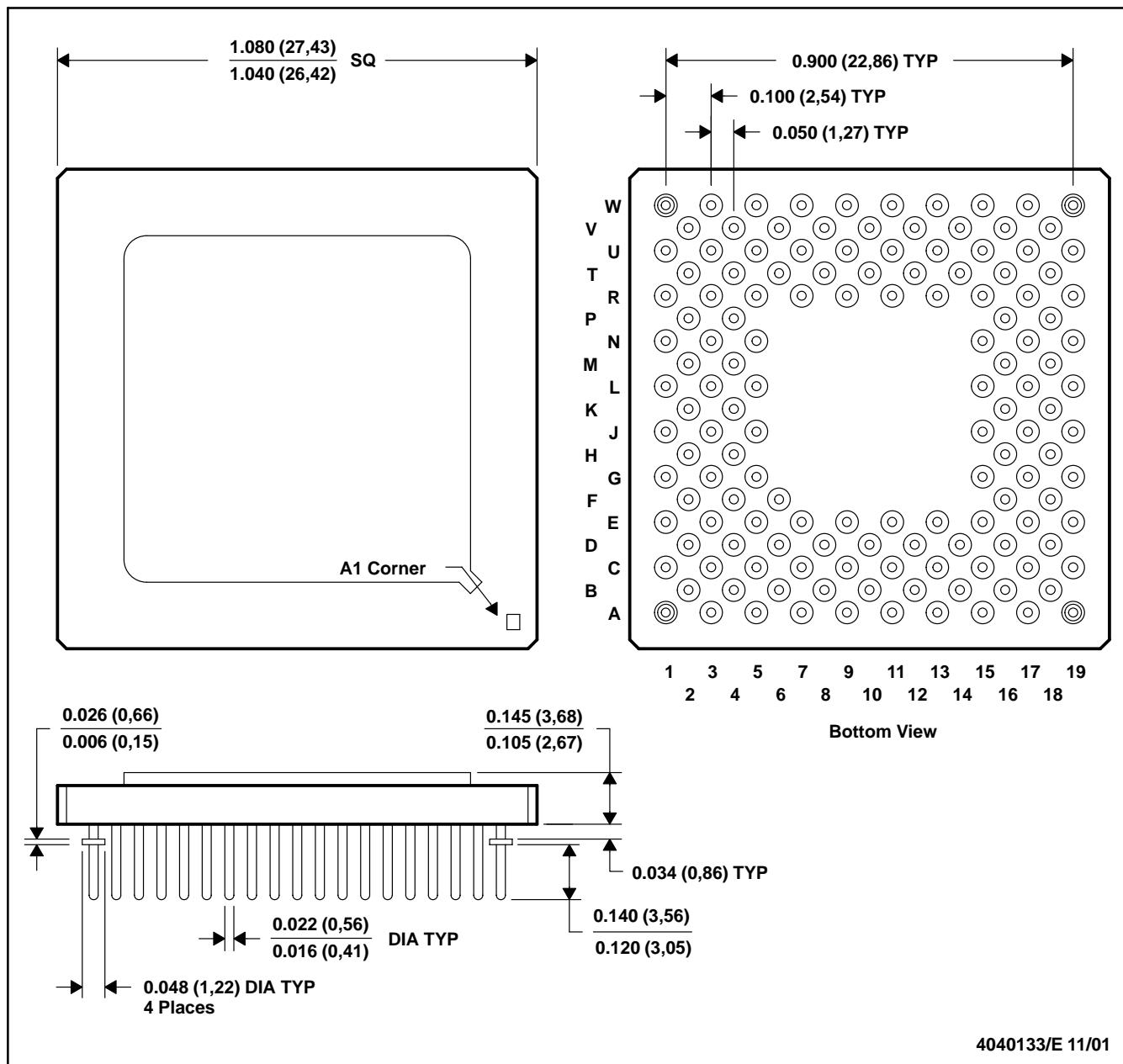


NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Ceramic quad flatpack with flat leads brazed to non-conductive tie bar carrier.
- D. This package is hermetically sealed with a metal lid.
- E. The leads are gold plated and can be solderdipped.
- F. Leads not shown for clarity purposes.
- G. Falls within JEDEC MO-113AC

GFA (S-CPGA-P141)

CERAMIC PIN GRID ARRAY



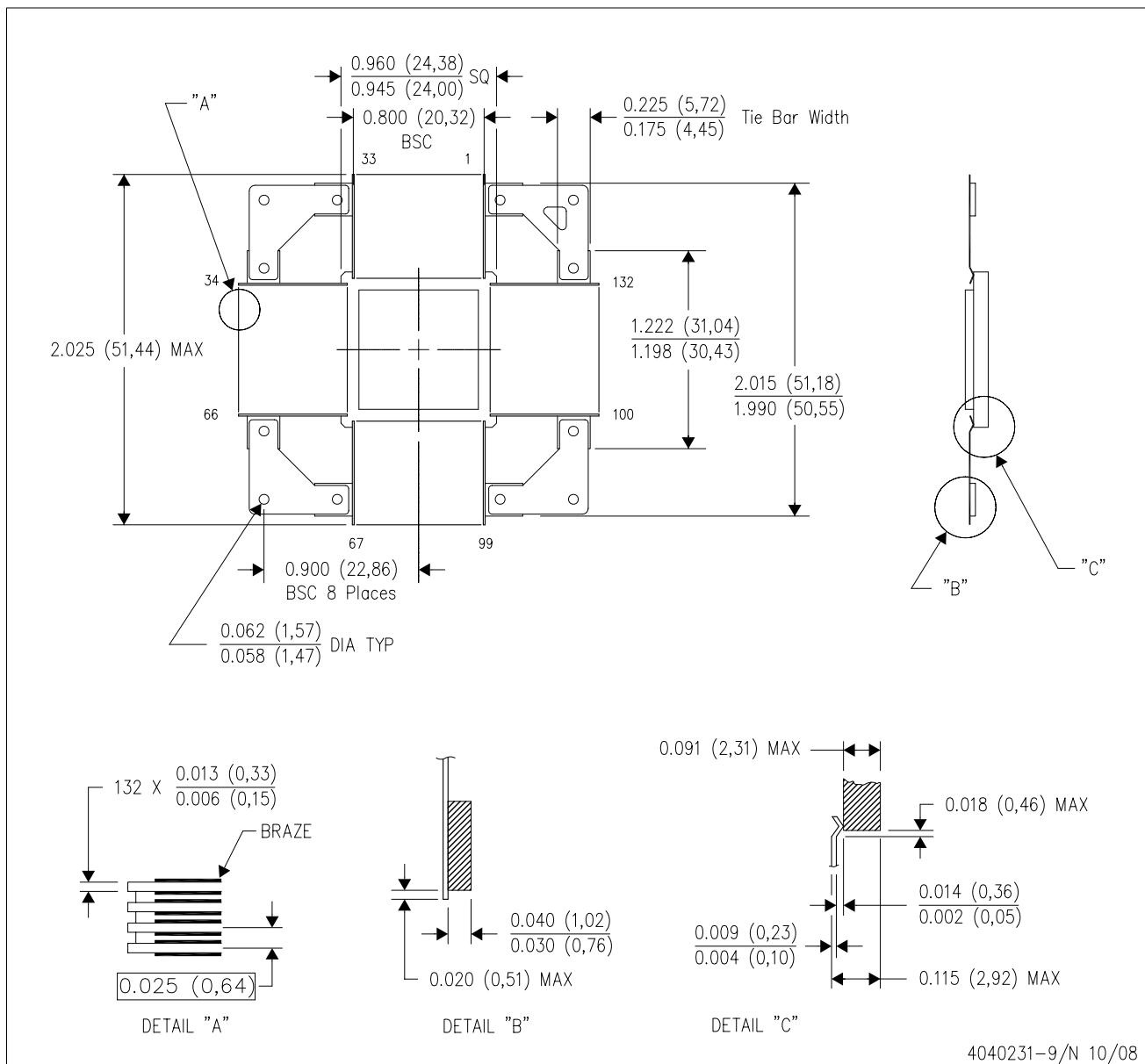
NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- Index mark can appear on top or bottom, depending on package vendor.
- Pins are located within 0.010 (0.25) diameter of true position relative to each other at maximum material condition and within 0.030 (0.76) diameter relative to the edge of the ceramic.
- This package can be hermetically sealed with metal lids or with ceramic lids using glass frit.
- The pins can be gold-plated or solder-dipped.
- Falls within JEDEC MO-128AB

4040133/E 11/01

HFG (S-CQFP-F132)

CERAMIC QUAD FLATPACK WITH NCTB



NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- Ceramic quad flatpack with flat leads brazed to non-conductive tie bar carrier.
- This package is hermetically sealed with a metal lid.
- The leads are gold plated and can be solderdipped.
- Leads not shown for clarity purposes.

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